

MVME8100

Installation and Use

P/N: 6806800P25F

June 2014



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About this Manual

Overview of Contents

This manual provides the information required to install and configure an MVME8100 . Additionally, this manual provides specific preparation and installation information and data applicable to the board.

The MVME8100 is a high-performance, dual core processor board featuring the Freescale QorIQ P5020 processor.

This manual is divided into the following chapters and appendices:

[Chapter 1, *Introduction*](#), lists the features of the MVME8100 baseboard, standard compliances, and model numbers for boards and accessories.

[Chapter 2, *Hardware Preparation and Installation*](#), includes a description of the MVME8100, unpacking instructions, environmental, thermal, and power requirements, and how to prepare and install the baseboard, transition module, and PMC module.

[Chapter 3, *Controls, LEDs, and Connectors*](#), provides an illustration of the board components and front panel details. This chapter also gives descriptions for the onboard and front panel LEDs and connectors.

[Chapter 4, *Functional Description*](#), describes the major features of the MVME8100 baseboard. These descriptions include both programming and hardware characteristics of major components.

[Chapter 5, *Boot System*, on page 91](#), describes the boot load software.

[Appendix A, *Battery Exchange*](#), describes the procedure for replacing a battery.

[Appendix B, *Related Documentation*](#), provides listings for publications, manufacturer's documents and related industry specification for this product.

[Safety Notes](#), contains the cautions and warnings applicable to the use of this product.

[Sicherheitshinweise](#), is a German translation of the Safety Notes chapter.

Abbreviations

This document uses the following abbreviations:

TERM	MEANING
A	Amps
AC	Alternating Current
ANSI	American National Standard Institute
BGA	Ball Grid Array
BLT	Block Transfer
CCB	Core Complex Bus
CE	Chip Enable
CFM	Cubic Feet per Minute
CMC	Common Mezzanine Card
COM	Communications
COP	Common On-chip Processor
CPLD	Complex Programmable Logic Device
CPU	Central Processing Unit
CRC	Cyclic Redundancy Check
DC	Direct Current
DDR	Double Data Rate
°C	Degrees Celsius
DIMM	Dual In-line Memory Module
DMA	Direct Memory Access
DRAM	Dynamic Random Access Memory
ECC	Error Correction Code
EEPROM	Electrically Erasable Programmable Read-Only Memory
eMMC	Enhanced Module Management Controller
FCC	Federal Communications Commission
FIFO	First In First Out

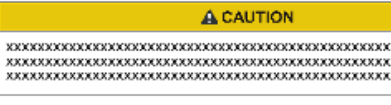
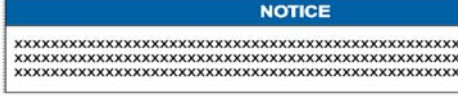
TERM	MEANING
fpBGA	Flip chip Plastic Ball Grid Array
GB	Gigabytes
Gbit	Gigabit
Gbps	Gigabits Per Second
GMII	Gigabit Media Independent Interface
ID	Identification
IEEE	Institute of Electrical and Electronics Engineers
I2C	Inter IC
IWD	Initial Hardware Watchdog
JTAG	Joint Test Access Group
KB	Kilobytes
KBAUD	Kilo Baud
LBC	Local Bus Controller
LCD	Liquid Crystal Display
LED	Light Emitting Diode
MB	Megabytes
Mbit	Megabit
Mbps	Megabits Per Second
MHz	Megahertz
MII	Media Independent Interface
MRAM	Magnetoresistive random-access memory
NAND	(Not and) Flash that is used for storage
OSWD	OS Watchdog
PBGA	Plastic Ball Grid Array
PCI	Peripheral Component Interconnect
PCI-X	Peripheral Component Interconnect -X
PIC	Programmable Interrupt Controller
PIM	PCI Mezzanine Card Input/Output Module

TERM	MEANING
PMC	PCI Mezzanine Card (IEEE P1386.1)
PLD	Programmable Logic Device
PLL	Phase-Locked Loop
POR	Power-On Reset
PrPMC	Processor PCI Mezzanine Card
QUART	Quad Universal Asynchronous Receiver/Transmitter
RGMII	Reduced Gigabit Media Independent Interface
ROM	Read-Only Memory
RTC	Real-Time Clock
RTM	Rear Transition Module
sATA	Serial AT Attachment
SBC	Single Board Computer
SDRAM	Synchronous Dynamic Random Access Memory
SMT	Surface Mount Technology
SODIMM	Small-Outline Dual In-line Memory Module
SPD	Serial Presence Detect
SRAM	Static Random Access Memory
TSEC	Three-Speed Ethernet Controller
2eSST	Two edge Source Synchronous Transfer
UART	Universal Asynchronous Receiver/Transmitter
USB	Universal Serial Bus
V	Volts
VITA	VMEbus International Trade Association
VME	VMEbus (Versa Module Eurocard)
VPD	Vital Product Data
W	Watts

Conventions

The following table describes the conventions used throughout this manual.

Notation	Description
0x00000000	Typical notation for hexadecimal numbers (digits are 0 through F), for example used for addresses and offsets
0b0000	Same for binary numbers (digits are 0 and 1)
bold	Used to emphasize a word
Screen	Used for on-screen output and code related elements or commands in body text
Courier + Bold	Used to characterize user input and to separate it from system output
<i>Reference</i>	Used for references and for table and figure descriptions
File > Exit	Notation for selecting a submenu
<text>	Notation for variables and keys
[text]	Notation for software buttons to click on the screen and parameter description
...	Repeated item for example node 1, node 2, ..., node 12
.	Omission of information from example/command that is not necessary at the time being
..	Ranges, for example: 0..4 means one of the integers 0,1,2,3, and 4 (used in registers)
	Logical OR

Notation	Description
 	Indicates a hazardous situation which, if not avoided, could result in death or serious injury
 	Indicates a hazardous situation which, if not avoided, may result in minor or moderate injury
	Indicates a property damage message
 	No danger encountered. Pay attention to important information

Summary of Changes

This is the first edition of the MVME8100 Single Board Computer Installation and Use.

Part Number	Publication Date	Description
6806800P25A	May 2012	First edition
6806800P25B	November 2012	GA release

Part Number	Publication Date	Description
6806800P25C	December 2012	Updated Standard Compliances on page 22
6806800P25D	September 2013	Updated Table 1-2 , Table 1-3 , Table 2-2 , Table 2-4 , PMC/XMC Installation on page 40, Table 3-3 on page 52, and Table 3-6 on page 55. Added Figure 2-2 on page 34, SATA Installation on page 43, Figure 2-4 on page 45, Figure 3-2 on page 50, Interrupt Controller Assignments on page 88 and GPIO Electrical Characteristics on page 89.
6806800P25E	December 2013	Added Chapter 5, Boot System , on page 91.
6806800P25F	June 2014	Re- branded to Artesyn template.

Introduction

1.1 Features

The MVME8100 Single Board Computer is a VMEbus board based on the Freescale QorIQ P5020 processor. It is a high performance 6U VME/VXS board targeted towards high-end military and industrial automation applications using VMEbus. The MVME8100 is compliant with the VITA standards VMEbus, 2eSST, and PCI-X.

Table 1-1 Features List

Function	Features
Processor (Subset of P5020 features used on MVME8100)	● Freescale QorIQ P5020 ● Two e5500 Power Architecture cores ● Five Gigabit Ethernet controllers (SGMII and RGMII interfaces) ● Two 64-bit DDR3/3L SDRAM memory controllers with ECC ● Multicore Programmable Interrupt Controller (PIC) ● Four I2C controllers ● Two 4-pin UARTs ● Two 4-channel DMA engines ● Enhanced local bus controller (eLBC) ● Two PCI Express controller/ports ● One Serial Rapid IO controller/ports (SRIO port) v1.3-compliant with features of v2.1 ● Enhanced secure digital host controller (SD/MMC) ● Enhance Serial Peripheral Interfaces (eSPI) ● Two high-speed USB 2.0 controllers with integrated PHYs
System Memory	● Two banks of DDR3 SDRAM with ECC ● Total 4 GB (2GB per Bank) ● 1333 MHz DDR3 data rate
SM Bus	● One 512 Kbit user configuration serial EEPROM ● 256B SPD EEPROMs ● One 64 Kbit VPD EEPROM ● RTC with battery backup ● Temperature Sensors ● RTM and XMC VPD EEPROMs

Table 1-1 Features List (continued)

Function	Features
FLASH	- Two soldered SPI FLASH, 8MB each, switchable for uboot primary/backup support - Hardware switch or Software bit write protection for entire logical bank - Eight GB eMMC Flash
NVRAM	512 KB MRAM
PCI Express	- Two 4X Ports to VXS backplane P0 (muxed with SRIO ports) - One 8X Port to PMC/XMC Site 1 - One 4X Port to PMC/XMC Site 2
SRIO	Two 4X Ports to VXS backplane P0 (muxed with PCIe ports)
USB	- One USB 2.0 for front panel I/O - Two USBs 2.0 for backplane RTM I/O
Ethernet	- One 10/100/1000BASE-T Ethernet port to front panel (only in air cooled variant) - Two 10/100/1000BASE-T Ethernet channels to P2 / RTM - Two 1000BASE-BX Ethernet SERDES channels to P0 backplane / RTM
Serial Ports	- One RS232/422/485 console port to front panel or P2 / RTM - Up to 4 RS232/422/485 COM ports to P2/ RTM
VME Bus	VME64x and 2eSST
Timers	- Eight 32-bit timers in CPU - Watchdog timer in CPU
PMC/XMC	Two PMC/XMC sites with 64-bit PMCIO on Site 1
SATA SSD	Option for one 2.5 inch SATA drive (PMC/XMC Site 2)
GPIO Interface	Four GPIOs to RTM
VXS Interface	- VXS (VITA 41) Specification compliant - Support backplane P0 connector
Form Factor	- Standard 6U, one slot - Support 0.8, and 0.85 inch slot chassis - Support heat frame on both sides for Conduction cooled board

Table 1-1 Features List (continued)

Function	Features
Miscellaneous	● One front panel RESET Switch ● LED front panel status indicators: four user/fail/ready LEDs ● Planar status indicators ● Boundary scan support
Software Support	● VxWorks OS support ● Linux OS support
RTM	Compatible with RTM (assembly # 0106852M***)
I/O	● One micro DB9 connector for console port on front panel ● One USB2.0 type A connector on front panel ● One front panel RJ45 connector with integrated LEDs for 10/100/1000 Ethernet channel ● PMC/XMC site 1 front I/O and rear PMC I/O ● PMC/XMC site two front I/O ● Four Serial ports to P2/RTM, two with micro DB9 connectors on RTM panel and two on planar headers ● Two 10/100/1000BASE-T Ethernet channels to RJ45 connectors on RTM panel ● Two 1000 BASE-BX Ethernet SERDES channels to backplane ● Two USB2.0 ports to RTM with USB type A connectors on RTM panel ● One SATA port to RTM with eSATA connector on RTM ● Four GPIOs to planar headers on RTM Note: The front panel I/O connectors are available only in ENP1 (air cooled variants). I/O signals in ENP4 (conduction cooled) variant are accessed through P2 only.

1.2 Standard Compliances

The MVME8100 is designed to be CE compliant and to meet the following standard requirements.

Table 1-2 Board Standard Compliances

Standard	Description
UL 60950-1 EN 60950-1 IEC 60950-1 CAN/CSA C22.2 No 60950-1	Safety Requirements (legal)
CISPR 22 EN 55022 EN 55024 FCC Class A VCCI Japan AS/NZS CISPR 22	EMC requirements (legal) on system level (predefined Artesyn system)
ETSI EN 300 019 series	Environmental Requirements
Directive 2002/95/EC	Directive on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS). The ENP1 version complies with RoHs 6 of 6. The ENP4 version complies with RoHS 5 of 6 due to lead solder used in the ENP4 heat frame.

Figure 1-1 Declaration of Conformity

EC Declaration of Conformity According to EN 17050-1:2004	
Manufacturer's Name:	Artesyn Embedded Computing Embedded Computing
Manufacturer's Address:	Zhongshan General Carton Box Factory Co. Ltd. No 62, Qi Guan Road West, Shiqi District, 528400 Zhongshan City Guangdong, PRC
Declares that the following product, in accordance with the requirements of 2004/108/EC, 2006/95/EC, 2011/65/ EU and their amending directives,	
Product:	MVME8100 Series VMEbus Single Board Computer
Model Name/Number:	MVME8100-202180404, MVME8100-202200401E, MVME8100-202200401S, MVME8100-202200404
has been designed and manufactured to the following specifications: EN55022: 2010 EN55024:2010 IEC 60950-1:2005 (2nd Edition), EN60950-1:2006+A11:2009 2011/65/EU RoHS Directive As manufacturer we hereby declare that the product named above has been designed to comply with the relevant sections of the above referenced specifications. This product complies with the essential health and safety requirements of the above specified directives. We have an internal production control system that ensures compliance between the manufactured products and the technical documentation.	
 Tom Tuttle, Manager, Product Testing Services 04/028/2014 Date (MM/DD/YYYY)  	

1.3 Mechanical Data

The MVME8100 is a full 6U board with added mounting holes to support an ENP4 board variant. The MVME8100 will occupy a single VME card slot.

Table 1-3 provides details on the board’s mechanical data.

Table 1-3 Mechanical Data

Characteristic	Value
Height	233.44 mm (9.2inches)
Depth	160.0 mm (6.3 inches)
Front Panel Height	261.8 mm (10.3 inches)
Width	19.8 mm (0.8 inches)
Maximum Component Height	14.8 mm (0.58 inches)
Weight (estimated)	0.58 Kg (ENP1) 0.90 Kg (ENP4)

1.4 Ordering Information

When ordering board variants or board accessories, use the order numbers given in the following tables.

1.4.1 Supported Board Models

Table 1-4 Board Variants

Marketing #	Processor
MVME8100-202200401E	P5020 2.0GHz 28W, 4GB DDR3, VXS, 2 PMC/XMC, IEEE, ENP1
MVME8100-202200401S	P5020 2.0GHz 28W, 4GB DDR3, VXS, 2 PMC/XMC, SCANBE, ENP1
MVME8100-202200404	P5020 1.8GHz 27W, 4GB DDR3, VXS, 2 PMC/XMC, ENP4

1.4.2 Board Accessories

This table lists the available expansion and transition modules for the MVME8100.

Model Number	Description
VXS1-RTM1	RTM for MVME8100 (supports ENP1 specifications only)
MVME8100-HDMNTKIT4	SSD Mounting kit (HDD not included)

Hardware Preparation and Installation

2.1 Overview

This chapter provides startup and safety instructions related to this product, hardware preparation instruction that includes default switch settings. System considerations and installation instructions for the baseboard, PMC, XMC, and Rear Transition Module (RTM) are also described in this chapter.

A fully implemented MVME8100 consists of the baseboard plus:

- Two single-wide or one double-wide PCI Mezzanine Card (PMC) slot for added versatility.
- One rear transition module for support of the mapped I/O from the MVME8100 baseboard to the P2 connector.
- Up to two optional XMC cards (in place of PMC modules).

The following table lists the things you need to do before using this board and explains where you can find the information for performing each step. Be sure to read this entire chapter, including all Caution and Warning notes, before you begin.

Table 2-1 Startup Overview

Task	Page
Unpack the hardware.	Unpacking and Inspecting the Board on page 28
Configure the hardware by setting jumpers on the board and RTM.	Configuring the Board on page 32
Install the RTM (VXS1-RTM1) of MVME8100 in the chassis.	Rear Transition Module on page 39
Install PMC module (if required).	Installing Accessories on page 39
Install XMC module (if required).	Installing Accessories on page 39
Install the MVME8100 in the chassis.	Installing and Removing the Board on page 46
Attach cabling and apply power.	Completing the Installation on page 48
Install PIM on transition module (if required).	Refer VXS1-RTM1 Installation and Use manual.
Examine and/or change environmental parameters.	<i>MVME8100 Single Board Computer Programmer's Reference</i>
Program the board as needed for your applications.	<i>MVME8100 Single Board Computer Programmer's Reference</i>

2.2 Unpacking and Inspecting the Board

Read all notices and cautions prior to unpacking the product.

NOTICE

Damage of Circuits

Electrostatic discharge and incorrect installation and removal can damage circuits or shorten their life.

Before touching the board or electronic components, make sure that you are working in an ESD-safe environment.

Shipment Inspection

To inspect the shipment, perform the following steps:

1. Verify that you have received all items of your shipment.
2. Check for damage and report any damage or differences to customer service.
3. Remove the desiccant bag shipped together with the board and dispose of it according to your country's legislation.



The product is thoroughly inspected before shipment. If any damage occurred during transportation or any items are missing, contact customer service immediately.

2.3 Requirements

Make sure that the board, when operated in your particular system configuration, meets the requirements specified in the next sections.

2.3.1 Environmental Requirements

The following table lists the currently available specifications for the environmental characteristics of the MVME8100. A complete functional description of the MVME8100 baseboard appears in [Chapter 4, Functional Description](#).

The MVME8100 has ENP1 and ENP4 variants which comply with the following environmental and regulatory specifications.



For ENP1 boards, the operating temperatures refer to the temperature of the air circulating around the board and not to the component temperature.

For ENP4 board, the operating temperature refers to the temperature at the card edge frame.

Table 2-2 MVME8100 Specifications

Characteristics	ENP1	ENP4
Cooling Method	Forced Air	Conduction
Operating temperature	0°C to +55°C	–40°C to +85° C
Storage Temperature	–40°C to +85°C	–55°C to +105°C Note: The MVME8100 ENP 4 version includes NAND Flash memory in the form of the eMMC. The specified storage limits for the MVME8100 ENP 4 version are –55°C to +105°C. However, it should be noted that the industry standard (for Flash) as well as the specific vendor of this component only warrants performance (without data degradation) from –40°C to +85°C. Storage of the MVME8100 outside this range (while supported by other components on the board) may result in an unspecified reduction in the data retention capabilities of the eMMC.
Relative humidity	To 95% RH	To 100% RH
Vibration Sine (10min/axis)	2G, 5 to 500Hz	10G, 15 to 2000Hz
Vibration Random (1hr/axis)	.002g/Hz, 15 to 2000Hz(2G RMS)	0.1g/Hz, 15 to 2000Hz (12GRMS)

Table 2-2 MVME8100 Specifications (continued)

Characteristics	ENP1	ENP4
Shock	20g/11mS	40g/11mS
Conformal Coating	No	Option (Acrylic)

NOTICE

Product Damage

High humidity and condensation on the board surface causes short circuits.

Do not operate the board outside the specified environmental limits.

Make sure the board is completely dry and there is no moisture on any surface before applying power.

2.3.2 Power Requirements

The MVME8100 uses the backplane +5V source to power each on board power supply. The +3.3V backplane supply is not utilized in order to have backward compatibility with old 3-row chassis. The -12V and +12V is routed through to the XMC and PMC connectors. The power estimates provided in the following table is the total board consumption from +5V, excluding the PMC/XMC, SATA HDD/SSD and USB devices.

Table 2-3 Operating Voltages

Voltages	Minimum	Normal	Maximum
+5.0V	4.875V (-2.5%)	5.0V	5.25V (+5%)

Table 2-4 Power Requirements

Board Variant	Power
MVME8100-202200401S/E (ENP1)	Board idle at OS prompt: 38 Watts, typical Operating load*: 42 Watts, typical 54 Watts, Max(@55°C) * Operating conditions: No RTM, PMC/XMC or peripherals.

Table 2-4 Power Requirements

Board Variant	Power
MVME8100-202180404 (ENP4)	Operating load*: 65 Watts, max (@85°C card edge temperature)

The following table shows the power limits due to the available 5 volts pins, when the MVME8100 is installed in either a 3-row or 5-row chassis and when PMCs/XMCs are present.

Chassis Type	Power Limit	Power limits PMCs or XMCs
3-Row	70 W maximum	Below 70 W ¹
5-Row	90 W maximum	Below 90 W ¹

1. Keep below power limit. Cooling limitations must be considered.

2.3.3 Thermal Requirements

The MVME8100 module requires a minimum air flow of 10 CFM uniformly distributed across the board, with the airflow traveling in the direction from PMC/XMC 1 to PMC/XMC 2, when operating at a 55°C (131°F) ambient temperature.

2.3.4 Thermally Significant Components

The chassis into which the MVME8100 is installed must provide sufficient airflow to maintain proper board operating temperature. The P5020 processor temperature should be monitored while the board is operational to ensure that the processor core temperature does not exceed 100°C. The processor core temperature can be read using the I2C sensor at address 0x4C on the processor I2C bus #1. For more information, refer *MVME8100 Single Board Computer Programmer's Reference*.

2.3.5 Equipment Requirements

The following equipment is recommended to complete an MVME8100 system:

- VMEbus system enclosure
- System console terminal
- Operating system (and/or application software)

2.4 Configuring the Board

To produce the desired configuration and ensure proper operation of the MVME8100, you may need to carry out certain hardware modifications before installing the module.

The MVME8100 provides software control over most options: by setting bits in control registers after installing the module in a system, you can modify its configuration.

Prior to installing PMC modules on the MVME8100 baseboard, ensure that all switches that are user configurable are set properly. To do this, refer to [Figure 2-1](#) or the board itself, for the location of specific switches and set the switches according to the following descriptions.

Figure 2-1 Switch Locations (ENP1 board)

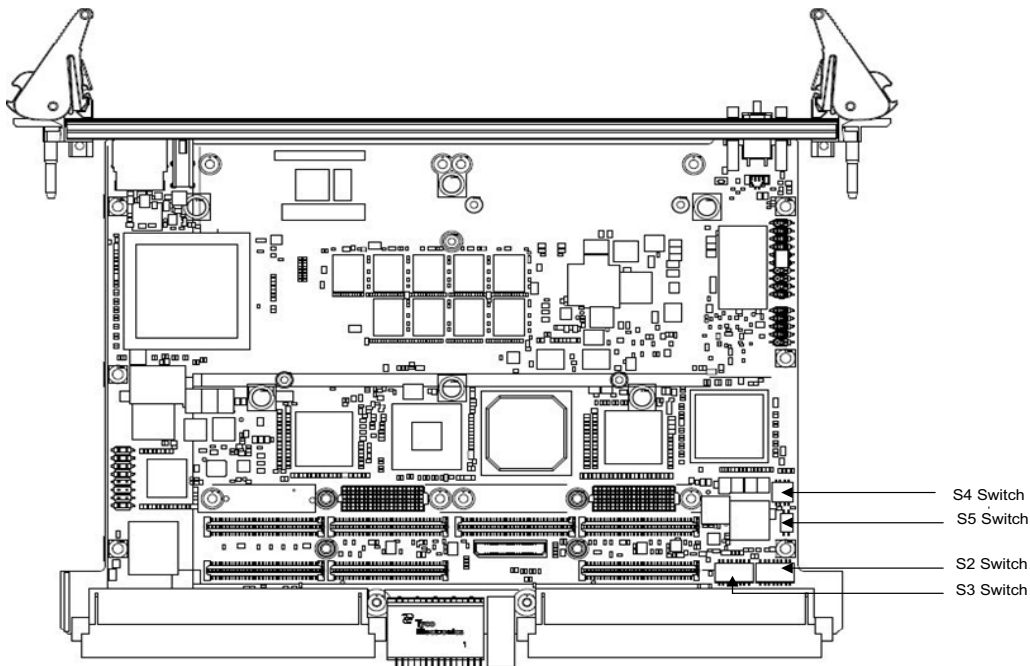
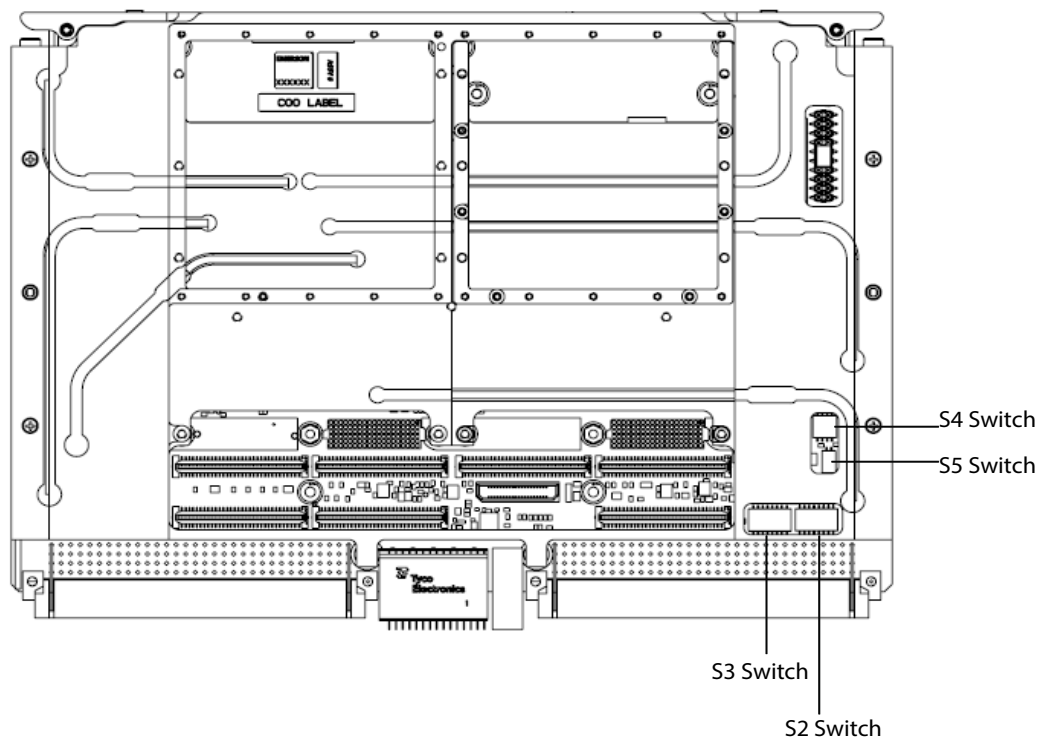


Figure 2-2 Switch Locations (ENP4 Board)



The following sections describe the on-board switches and their configurations for the MVME8100.

NOTICE

Board Malfunction

Switches marked as “reserved” might carry production-related functions and can cause the board to malfunction if their setting is changed.

Do not change settings of switches marked as “reserved”. The setting of switches which are not marked as “reserved” has to be checked and changed before board installation.

2.4.1 Configuration Switches

The board provides the following configuration switches:

- S2 Switch
- S3 Switch
- S4 Switch
- S5 Switch
- Reset/Abort Switch

2.4.1.1 S2 Switch

The Switch Bank S2 provides watchdog control, serial port configuration and P0 fabric selection.

Table 2-5 S2 Switch Settings

Position	Default	Description
1	OFF	OFF - Watchdog Disabled ON - Watchdog Enabled
2	OFF	OFF - Serial Console Port to Front Panel ON - Serial Console Port to P2/RTM panel
3	OFF	OFF - P2 Serial Port 0 is RS232 ON - P2 Serial Port 0 is RS422/485
4	OFF	OFF - P2 Serial Port 1 is RS232 ON - P2 Serial Port 1 is RS422/485
5	OFF	OFF - P2 Serial Port 2 is RS232 ON - P2 Serial Port 2 is RS422/485
6	OFF	OFF - P2 Serial Port 3 is RS232 ON - P2 Serial Port 3 is RS422/485
7	OFF	OFF - Front Panel console Port is RS232 ON - Front Panel console Port is RS422/485
8	OFF	OFF - Select SRIO for P0 Backplane Fabric ON - Select PCIe for P0 Backplane Fabric

2.4.1.2 S3 Switch

The TSI148 VMEbus Status Register provides the VMEbus geographical address of the MVME8100. Applications not using a 5-row backplane can use these switches to manually assign board's VMEbus geographical address. Note that this switch is wired parallel with geographical address pins on the 5-row connector to these switches must be in the off position when installed in a 5-row chassis in order to get the correct address from P1 connector. This switch reflects the inverted states on the geographical address signals.

Table 2-6 S3 Switch Settings

Position	Default	Description
1	OFF	OFF - SPI FLASH Write Protect is Disabled ON - SPI FLASH Write Protect is Enabled
2	OFF	P0 Connector Port B PCIE/SRIO Fabric Selection OFF- Port B same as Port A selection and is controlled by SW2-8 ON - Port B selection is opposite of SW2-8 selection
3	OFF (1)	GAP#
4	OFF (1)	GA4#
5	OFF (1)	GA3#
6	OFF (1)	GA2#
7	OFF (1)	GA1#
8	OFF (1)	GA0#

Below is the switch configuration for corresponding slot address in a 21 slot chassis 3-row backplane.

Table 2-7 Three Row Backplane Manual Slot Addressing

S1-3	S1-4	S1-5	S1-6	S1-7	S1-8	GAP# GA(4:0)#	Slot Address
OFF	OFF	OFF	OFF	OFF	ON	1 11110	1
OFF	OFF	OFF	OFF	ON	OFF	1 11101	2
ON	OFF	OFF	OFF	ON	ON	0 11100	3
OFF	OFF	OFF	ON	OFF	OFF	1 11011	4

Table 2-7 Three Row Backplane Manual Slot Addressing

S1-3	S1-4	S1-5	S1-6	S1-7	S1-8	GAP# GA(4:0)#	Slot Address
ON	OFF	OFF	ON	OFF	ON	0 11010	5
ON	OFF	OFF	ON	ON	OFF	0 11001	6
OFF	OFF	OFF	ON	ON	ON	1 11000	7
OFF	OFF	ON	OFF	OFF	OFF	1 10111	8
ON	OFF	ON	OFF	OFF	ON	0 10110	9
ON	OFF	ON	OFF	ON	OFF	0 10101	10
OFF	OFF	ON	OFF	ON	ON	1 10100	11
ON	OFF	ON	ON	OFF	OFF	0 10011	12
OFF	OFF	ON	ON	OFF	ON	1 10010	13
OFF	OFF	ON	ON	ON	OFF	1 10001	14
ON	OFF	ON	ON	ON	ON	0 10000	15
OFF	ON	OFF	OFF	OFF	OFF	1 01111	16
ON	ON	OFF	OFF	OFF	ON	0 01110	17
ON	ON	OFF	OFF	ON	OFF	0 01100	18
OFF	ON	OFF	OFF	ON	ON	1 01100	19
ON	ON	OFF	ON	OFF	OFF	0 01011	20
OFF	ON	OFF	ON	OFF	ON	1 01010	21

2.4.1.3 S4 Switch

The S4 switch includes the SCON control and PCIe/SRIO P0 root complex/endpoint configuration switches. The VME SCON AUTO switch is OFF to select Auto-SCON mode. The switch is ON to select manual SCON mode which works in conjunction with the VME SCON SEL switch. The VME_SCON_SEL switch is OFF to manually select SCON mode. This switch is ON to manually select non-SYSCON mode. This switch is only effective when the VME SCON AUTO switch is ON.

Table 2-8 S4 Switch Settings

Position	Default	Description
1	OFF	Clear Environment Variables OFF - Disable Clear Environment Variables ON - Enable Clear Environment Variables. At reset, uboot ENV variables are set to default values.
2	OFF	OFF - Configure PCIe/SRIO Switches as P0 Root Complex ON - Configure PCIe/SRIO Switches as P0 Endpoint
3	OFF	OFF - Auto VME System Controller ON - Manual VME System Controller
4	OFF	OFF - VME System Controller ON - VME Non-System Controller

2.4.1.4 S5 Switch

The switch Bank S5 provides the boot SPI FLASH selection.

Table 2-9 S5 Switch Settings

Position	Default	Description
1	OFF	OFF - Boot from SPI FLASH 0 ON - Boot from SPI FLASH 1
2	OFF	Reserved

2.4.1.5 Reset /Abort Switch

A dual function switch can be found in the front panel. This switch can function either as a Reset or Abort button. If the button is pressed for less than 3 seconds, the CPLD will generate an abort interrupt to the P5020 processor. If the button is pressed for more than 3 seconds, the CPLD will generate a board hard reset. If the board is configured as System Controller, the backplane VME SYSRESET signal is also asserted during a board hard reset.

2.5 Installing Accessories

This section describes the procedures for installing the RTM of MVME8100, PMCs, and the XMCspan on the baseboard.

2.5.1 Rear Transition Module

The RTM of MVME8100 does not support hot swap, You must remove power to the system before installing the module. Before installing the transition module, you may need to manually configure the RTM switches and install a PMC I/O Module (PIM).

NOTICE

Damage of Circuits

Electrostatic discharge and incorrect installation and removal can damage circuits or shorten their life.

Before touching the board or electronic components, make sure that you are working in an ESD-safe environment.

Product Damage

Only use injector handles for board insertion to avoid damage to the front panel and/or PCB. Deformation of the front panel can cause an electrical short or other board malfunction.

Board Malfunction

Switches marked as “reserved” might carry production-related functions and can cause the board to malfunction if their setting is changed.

Do not change settings of switches marked as “reserved”. The setting of switches which are not marked as “reserved” has to be checked and changed before board installation.

Installation and Removal Procedure

To begin the installation of the RTM in a chassis, proceed as follows:

1. Turn all equipment power OFF and disconnect the power cable from the AC power source.
2. Remove the chassis cover as instructed in the equipment user's manual.
3. Remove the filler panel(s) from the appropriate card slot(s) at the rear of the chassis (if the chassis has a rear card cage).
4. Install the top and bottom edge of the RTM into the rear guides of the chassis.
5. Ensure that the levers of the two injector/ejectors are in the outward position.
6. Slide the RTM into the chassis until resistance is felt.
7. Simultaneously move the injector/ejector levers in an inward direction.
8. Verify that the RTM is properly seated and secure it to the chassis using the two screws located adjacent to the injector/ejector levers.
9. Connect the appropriate cables to the RTM.

To remove the RTM from the chassis, reverse the procedure and press the red locking tabs (IEEE handles only) to extract the board.

2.5.2 PMC/XMC Installation

The PMC connectors are placed to support two single-width PMCs or one double-width PMC. PMC site 1 supports front PMC I/O and rear PMC I/O via the Jn4 connector. PMC 1 I/O is routed to the VME P2 connector. PMC site 2 only supports front PMC I/O and does not have a Jn4 connector. The PMC 1 Jn4 user I/O signals only support low-current high-speed signals and thus do not support current-bearing power supply usage.

The user-configured switches are accessible with the PMC/XMCs installed. The onboard PMC sites are configured to support +3.3 V I/O PMC modules. The onboard PMC sites do not support +5.0 V I/O PMC modules.

The ENP4 version only supports rugged conduction cooled PMC/XMC modules (see VITA 20-2001 for conduction cooled PMC for mechanical definition).

Follow these steps to install a PMC/XMC module onto the MVME8100 board.

Installation Procedure

Read all notices and follow these steps to install a PMC/XMC on the baseboard.

NOTICE

Logic Ground to Chassis Ground Isolation

The MVME8100 ENP1 and ENP4 heat frames are isolated from the board logic ground. Installing a PMC or XMC module which has mounting locations connected to the module logic ground will result in a short between chassis ground and the MVME8100 logic ground.

Damage of Circuits

Electrostatic discharge and incorrect installation and removal can damage circuits or shorten their life.

Before touching the board or electronic components, make sure that you are working in an ESD-safe environment.

Product Damage

Inserting or removing modules with power applied may result in damage to module components.

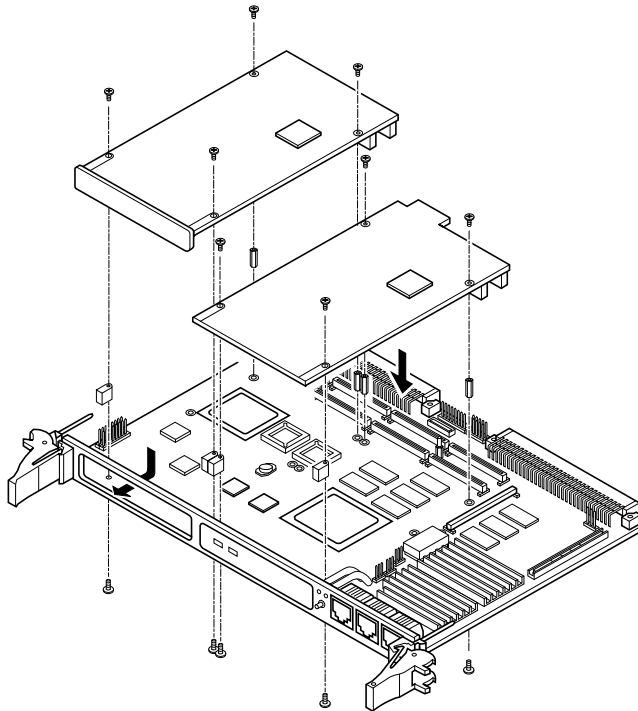
Before installing or removing additional devices or modules, read the documentation that came with the product.

1. Attach an ESD strap to your wrist. Attach the other end of the strap to the chassis as a ground. Make sure that it is securely fastened throughout the procedure.
2. If the PMC/XMC has a front filler panel, remove the PMC/XMC filler plate from the front panel cut-out.
3. Remove the two rear stand-offs from the PMC/XMC. The MVME8100 heat frame has built-in rear stand-offs.

4. Slide the front bezel of the PMC/XMC into the cut-out from behind. The front bezel of the PMC/XMC module will be flushed with the board when the connectors on the module align with the mating connectors on the board.
Note: ENP4 PMC/XMC modules do not have front bezels.
5. Align the mating connectors properly and apply minimal pressure to the PMC/XMC until it is seated to the board.
6. Insert the two front PMC/XMC mounting screws through the mounting holes on the bottom side of the board, and then install the top side screws. Tighten the screws.
Note: Rugged PMC/XMC modules installed on an ENP4 MVME8100 have more than four mounting screws.
7. Install the board into the appropriate card slot. Make sure that the board is well seated into the backplane connectors. Do not damage or bend connector pins.

8. Replace the chassis or system cover.
9. Reconnect the system to the power source and then turn on the system.

Figure 2-3 Typical Placement of a PMC/XMC Module on a VME Module



2.5.3 SATA Installation

A 2.5" SATA drive can be installed in PMC/XMC site 2. The MVME8100-HDMTKIT4 SATA mounting kit (6706881A01x) provides the mounting hardware. A SATA drive which meets the intended board operating environment for temperature and vibration must be used.

Read all notices and follow these steps to install a SATA drive on the baseboard.

NOTICE

Logic Ground to Chassis Ground Isolation

The MVME8100 ENP1 and ENP4 heat frames are isolated from the board logic ground. Installing a SATA drive which has a metallic case connected to the drive logic ground will result in a short between chassis ground and the MVME8100 logic ground.

Damage of Circuits

Electrostatic discharge and incorrect installation and removal can damage circuits or shorten their life.

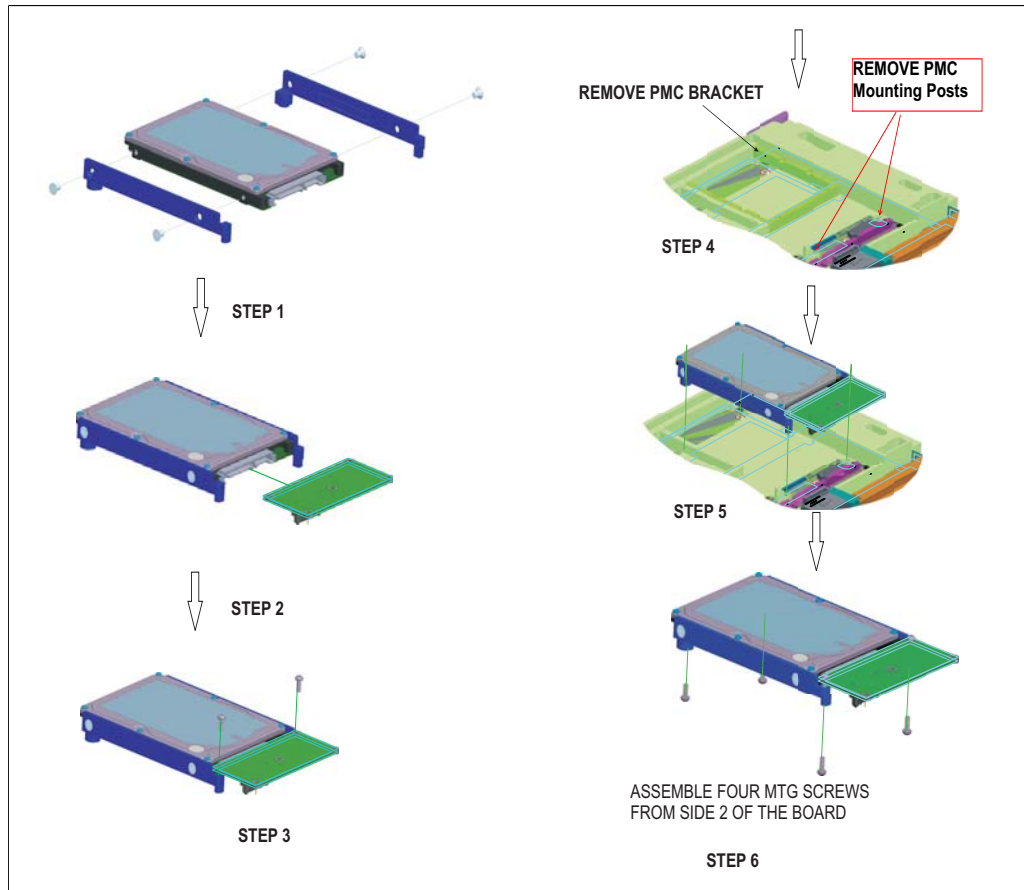
Before touching the board or electronic components, make sure that you are working in an ESD- safe environment.

Product Damage

Inserting or removing modules with power applied may result in damage to module components.

Before installing or removing additional devices or modules, read the documentation that came with the product.

Figure 2-4 SATA drive Installation



Use the following steps to install a SATA drive:

1. Wear an ESD strap to your wrist and fix the other end of the ESD strap to an electrical ground.
2. Secure mounting brackets to each side of SATA drive as shown in step 1 of Figure 2-4.
3. Attach SATA adapter board to SATA drive as shown in step 2 of Figure 2-4.
4. Use two screws to secure adapter to mounting brackets as shown in step 3 of Figure 2-4.

5. Remove PMC/XMC bracket and mounting posts from site 2 as shown in step 4 of Figure 2-4.
6. Attach SATA drive assembly with adapter board and mounting brackets to MVME8100 board at PMC/XMC site 2 as shown in step 5 of Figure 2-4. Make sure that the SATA adapter connector is fully mated with the board SATA connector.
7. Secure SATA drive assembly to board using four screws inserted from the bottom side of the board as shown in step 5 of Figure 2-4.

2.6 Installing and Removing the Board

This section describes the recommended procedure for installing the MVM8100 board in a chassis. The MVME8100 does not support hot swap, you must remove power to the slot or system before installing the module. Before installing the MVME8100, ensure that the serial ports and switches are properly configured.

Installation and Removal Procedure

Before you install your module, please read all cautions, warnings and instructions presented in this section.

NOTICE

Damage of Circuits

Electrostatic discharge and incorrect installation and removal can damage circuits or shorten their life.

Before touching the board or electronic components, make sure that you are working in an ESD-safe environment.

Product Damage

Only use injector handles for board insertion to avoid damage to the front panel and/or PCB. Deformation of the front panel can cause an electrical short or other board malfunction.

Use the following steps to install the MVME8100 into your computer chassis.

1. Wear an ESD strap to your wrist.
2. Attach the other end of the ESD strap to an electrical ground. The ESD strap must be secured to your wrist and to ground throughout the procedure.
3. Remove any filler panel that might fill the slot.
4. Install the top and bottom edge of the MVME8100 into the guides of the chassis.
5. Ensure that the levers of the two IEEE locking injector/ejectors (if equipped) are in the unlocked outward position.
6. Slide the MVME8100 into the chassis until you feel resistance.
7. Simultaneously move the injector/ ejector levers (if equipped) in an inward direction until locked. If fitted with SCANBE ejectors, adjust them inward and apply pressure to them to seat the board.
8. Verify that the MVME8100 is properly installed and secure it to the chassis using the two screws located adjacent to the injector/ejector levers.
9. When installing an ENP4 version board, the maximum torque that should be used on the wedge lock screws is 6 in-lbs.
10. Connect the appropriate cables to the MVME8100.

When the MVME8100 (and optionally, an RTM) is installed in a chassis, you are ready to connect peripherals and apply power to the slot or system.

The front-panel Micro-DB9 connector provides a console interface to U-boot. It presents an RS-232 DTE interface (TX/RX/ CTS/RTS). The default serial configuration is 9600/8/N/1. This mates with an ITT MDSM-9SC-Z11 (or equivalent). The Artesyn part number SERIAL-MINI-D2 converts this to a standard male DB9 interface.

To remove the board from the chassis, reverse the procedure and press the red locking tabs (IEEE handles only) to extract the board.

2.7 Completing the Installation

The MVME8100 is designed to operate as an application-specific compute blade or an intelligent I/O board/carrier. It can be used in any slot in a VME chassis. When the MVME8100 is installed in a chassis, you are ready to connect peripherals and apply power to the board.

Figure 3-1 on page 49 show the locations of the various connectors on the MVME8100.

NOTICE

Product Damage

RJ-45 connectors on modules are either twisted-pair Ethernet (TPE) or E1/T1/J1 network interfaces. Connecting an E1/T1/J1 line to an Ethernet connector may damage your system.

- Make sure that TPE connectors near your working area are clearly marked as network connectors.
- Verify that the length of an electric cable connected to a TPE bushing does not exceed 100 meters.
- Make sure the TPE bushing of the system is connected only to safety extra low voltage circuits (SELV circuits).

If in doubt, ask your system administrator.

The console settings for the MVME8100 are:

- Eight bits per character
- One stop bit per character
- Parity disabled (no parity)
- Baud rate of 9600 baud

Verify that hardware is installed and the power/peripheral cables connected are appropriate for your system configuration.

Replace the chassis or system cover, reconnect the chassis to the AC or DC power source, and turn the equipment power on.

Controls, LEDs, and Connectors

3.1 Overview

This chapter summarizes the controls, LEDs and connectors for the MVME8100 baseboard.

3.2 Front Panel

The following switch, LEDs, and connectors are available on the MVME8100 front panel. Refer to [Figure 3-1](#) for the location of each.

Figure 3-1 ENP1 Board Front Panel LEDs, Connectors, Switch

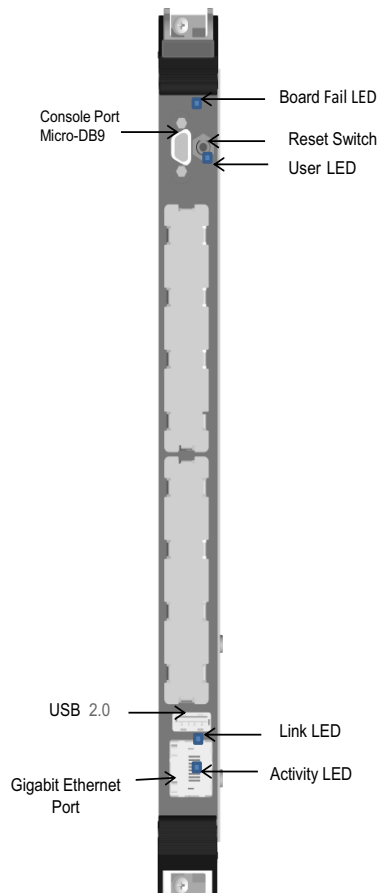
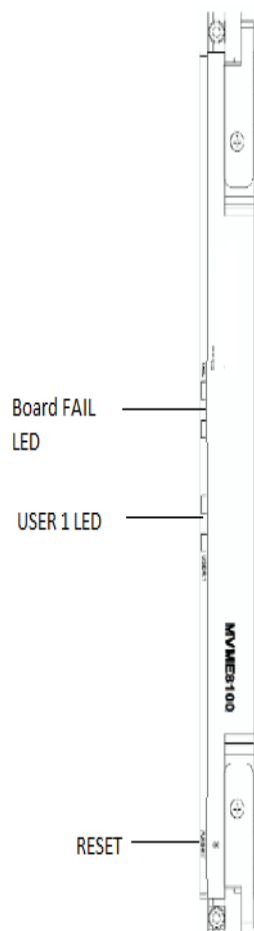


Figure 3-2 ENP4 Front Panel LEDs



3.2.1 LEDS

3.2.1.1 Front Panel LEDs

Table 3-1 describes the LEDs on the front panel of the MVME8100. Refer to Figure 3-1 for LED locations.

Table 3-1 Front Panel LEDs

Label	Function	Color	Description
USER 1	User Defined	Off	By Default
		Yellow	User Software Controllable.
		Red	User Software Controllable.
FAIL	Board Fail	Off	Normal operation after successful firmware boot
		Red	One or more on-board power rails have failed and the board has shutdown to protect the hardware. Normal during power up, during hardware reset (such as a front panel reset). May be asserted by the BDFAIL bit in the Tsi148 VSTAT register
SPEED	Link/Speed	Off	No link
		Amber	10/100BASE-T operation
		Green	1000 BASE-T operation
ACT	Activity	Off	No activity
		Blinking Green	Activity proportional to bandwidth utilization

3.2.2 Connectors

This section describes the pin assignments and signals for the connectors on the MVME8100.

3.2.2.1 External Connectors

3.2.2.1.1 Front Panel Connectors

The following are the Front Panel Connectors:

- Serial Console Port (J1)
- Front Panel Ethernet Connector (J1)
- USB Connector (J5)

Table 3-2 Console Front Panel Connector (J1)

PIN No	RS232 SIGNALING	RS485 SIGNALING
1	NC	NC
2	COM_0_RX	COM_0_RX-
3	COM_0_TX	COM_0_TX-
4	NC	NC
5	GND	GND
6	NC	NC
7	COM_0_RTS	COM0_TX+
8	COM_0_CTS	COM0_RX+
9	NC	NC

Table 3-3 Front Panel Tri-Speed Ethernet Connector (J1)

Pin No	Signal Description
1	TD0+
2	TD0-
3	TD1+
4	TD2+

Table 3-3 Front Panel Tri-Speed Ethernet Connector (J1)

Pin No	Signal Description
5	TD2-
6	TD1-
7	TD3+
8	TD3-

Table 3-4 USB Connector (J5)

Pin No	Signal Description
1	+5V
2	Data -
3	Data +
4	GND

3.2.2.1.2 Backplane Connectors

Table 3-5 P1 Connectors

P1 Connector (1st Row)		P1 Connector (2nd Row)		P1 Connector (3rd Row)		P1 Connector (4th Row)		P1 Connector (5th Row)	
Pin Name	Signal Description	Pin Name	Signal Description	Pin Name	Signal Description	Pin Name	Signal Description	Pin Name	Signal Description
A1	DATA 0	B1	BBSY	C1	DATA 8	D1	+5V	Z1	NC
A2	DATA 1	B2	BCLR	C2	DATA 9	D2	GND	Z2	GND
A3	DATA 2	B3	ACFAIL	C3	DATA 10	D3	NC	Z3	NC
A4	DATA 3	B4	BGIN0	C4	DATA 11	D4	NC	Z4	GND
A5	DATA 4	B5	BGOUT0	C5	DATA 12	D5	NC	Z5	NC
A6	DATA 5	B6	BGIN1	C6	DATA 13	D6	NC	Z6	GND
A7	DATA 6	B7	BGOUT1	C7	DATA 14	D7	NC	Z7	NC

Table 3-5 P1 Connectors

P1 Connector (1st Row)		P1 Connector (2nd Row)		P1 Connector (3rd Row)		P1 Connector (4th Row)		P1 Connector (5th Row)	
Pin Name	Signal Description	Pin Name	Signal Description	Pin Name	Signal Description	Pin Name	Signal Description	Pin Name	Signal Description
A8	DATA 7	B8	BGIN2	C8	DATA 15	D8	NC	Z8	GND
A9	GND	B9	BGOUT2	C9	GND	D9	GAP	Z9	NC
A10	SYSCLK	B10	BGIN3	C10	SYSFAIL	D10	GA0	Z10	GND
A11	GND	B11	BGOUT3	C11	BERR	D11	GA1	Z11	NC
A12	DS1	B12	BR0	C12	SYSRESET	D12	+3.3V (not used)	Z12	GND
A13	DS0	B13	BR1	C13	LWORD	D13	GA2	Z13	NC
A14	WRITE	B14	BR2	C14	AM 5	D14	+3.3V (not used)	Z14	GND
A15	GND	B15	BR3	C15	ADD 23	D15	GA3	Z15	NC
A16	DTACK	B16	AM 0	C16	ADD 22	D16	+3.3V (not used)	Z16	GND
A17	GND	B17	AM 1	C17	ADD 21	D17	GA4	Z17	NC
A18	AS	B18	AM 2	C18	ADD 20	D18	+3.3V (not used)	Z18	GND
A19	GND	B19	AM 3	C19	ADD 19	D19	NC	Z19	NC
A20	IACK	B20	GND	C20	ADD 18	D20	+3.3V (not used)	Z20	GND
A21	IACKIN	B21	NC	C21	ADD 17	D21	NC	Z21	NC
A22	IACKOUT	B22	NC	C22	ADD 16	D22	+3.3V (not used)	Z22	GND
A23	AM 4	B23	GND	C23	ADD 15	D23	NC	Z23	NC
A24	ADD 7	B24	IRQ7	C24	ADD 14	D24	+3.3V (not used)	Z24	GND
A25	ADD 6	B25	IRQ6	C25	ADD 13	D25	NC	Z25	NC
A26	ADD 5	B26	IRQ5	C26	ADD 12	D26	+3.3V (not used)	Z26	GND

Table 3-5 P1 Connectors

P1 Connector (1st Row)		P1 Connector (2nd Row)		P1 Connector (3rd Row)		P1 Connector (4th Row)		P1 Connector (5th Row)	
Pin Name	Signal Description	Pin Name	Signal Description	Pin Name	Signal Description	Pin Name	Signal Description	Pin Name	Signal Description
A27	ADD 4	B27	IRQ4	C27	ADD 11	D27	NC	Z27	NC
A28	ADD 3	B28	IRQ3	C28	ADD 10	D28	+3.3V (not used)	Z28	GND
A29	ADD 2	B29	IRQ2	C29	ADD 9	D29	NC	Z29	NC
A30	ADD 1	B30	IRQ1	C30	ADD 8	D30	+3.3V (not used)	Z30	GND
A31	-12V	B31	NC	C31	+12V	D31	GND	Z31	NC
A32	+5V	B32	+5V	C32	+5V	D32	+5V	Z32	GND

Table 3-6 P2 Connectors

P2 Connector (1st Row)		P2 Connector (2nd Row)		P2 Connector (3rd Row)		P2 Connector (4th Row)		P2 Connector (5th Row)	
Pin Name	Signal Description	Pin Name	Signal Description	Pin Name	Signal Description	Pin Name	Signal Description	Pin Name	Signal Description
A1	PMC IO 2	B1	+5V	C1	PMC IO 1	D1	NC	Z1	GIGE3_MD IO0_P
A2	PMC IO 4	B2	GND	C2	PMC IO 3	D2	NC	Z2	GND
A3	PMC IO 6	B3	RETRY	C3	PMC IO 5	D3	GND	Z3	GIGE3_MD IO0_N
A4	PMC IO 8	B4	ADDRESS 24	C4	PMC IO 7	D4	USB1_P	Z4	GND
A5	PMC IO 10	B5	ADDRESS 25	C5	PMC IO 9	D5	USB1_N	Z5	GIGE3_MD IO1_P
A6	PMC IO 12	B6	ADDRESS 26	C6	PMC IO 11	D6	GND	Z6	GND
A7	PMC IO 14	B7	ADDRESS 27	C7	PMC IO 13	D7	USB2_P	Z7	GIGE3_MD IO1_N

Table 3-6 P2 Connectors

P2 Connector (1st Row)		P2 Connector (2nd Row)		P2 Connector (3rd Row)		P2 Connector (4th Row)		P2 Connector (5th Row)	
Pin Name	Signal Description	Pin Name	Signal Description	Pin Name	Signal Description	Pin Name	Signal Description	Pin Name	Signal Description
A8	PMC IO 16	B8	ADDRESS 28	C8	PMC IO 15	D8	USB2_N	Z8	GND
A9	PMC IO 18	B9	ADDRESS 29	C9	PMC IO 17	D9	RTM_SIO	Z9	GIGE3_MD IO2_P
A10	PMC IO 20	B10	ADDRESS 30	C10	PMC IO 19	D10	BPSWITCH_N	Z10	GND
A11	PMC IO 22	B11	ADDRESS 31	C11	PMC IO 21	D11	GPIO_2	Z11	GIGE3_MD IO2_N
A12	PMC IO 24	B12	GND	C12	PMC IO 23	D12	GPIO_3	Z12	GND
A13	PMC IO 26	B13	+5V	C13	PMC IO 25	D13	I2C DATA	Z13	GIGE3_MD IO3_P
A14	PMC IO 28	B14	DATA 16	C14	PMC IO 27	D14	I2C CLK	Z14	GND
A15	PMC IO 30	B15	DATA 17	C15	PMC IO 29	D15	COM1_RX/ COM1_RX_N	Z15	GIGE3_MD IO3_N
A16	PMC IO 32	B16	DATA 18	C16	PMC IO 31	D16	COM1_CTS_N/ COM1_RX_P	Z16	GND
A17	PMC IO 34	B17	DATA 19	C17	PMC IO 33	D17	COM2_RX/ COM2_RX_N	Z17	GIGE4_MD IO0_P
A18	PMC IO 36	B18	DATA 20	C18	PMC IO 35	D18	COM2_CTS_N/ COM2_RX_P	Z18	GND
A19	PMC IO 38	B19	DATA 21	C19	PMC IO 37	D19	COM3_RX/ COM3_RX_N	Z19	GIGE4_MD IO0_N
A20	PMC IO 40	B20	DATA 22	C20	PMC IO 39	D20	COM3_CTS_N/ COM3_RX_P	Z20	GND

Table 3-6 P2 Connectors

P2 Connector (1st Row)		P2 Connector (2nd Row)		P2 Connector (3rd Row)		P2 Connector (4th Row)		P2 Connector (5th Row)	
Pin Name	Signal Description	Pin Name	Signal Description	Pin Name	Signal Description	Pin Name	Signal Description	Pin Name	Signal Description
A21	PMC IO 42	B21	DATA 23	C21	PMC IO 41	D21	COM4_RX/ COM4_RX_ N	Z21	GIGE4_MD IO1_P
A22	PMC IO 44	B22	GND	C22	PMC IO 43	D22	COM4_CTS _N/COM4_ RX_P	Z22	GND
A23	PMC IO 46	B23	DATA 24	C23	PMC IO 45	D23	COM1_TX/ COM1_TX_ N	Z23	GIGE4_MD IO1_N
A24	PMC IO 48	B24	DATA 25	C24	PMC IO 47	D24	COM1_RTS _N/COM1_ TX_P	Z24	GND
A25	PMC IO 50	B25	DATA 26	C25	PMC IO 49	D25	COM2_TX/ COM2_TX_ N	Z25	GIGE4_MD IO2_P
A26	PMC IO 52	B26	DATA 27	C26	PMC IO 51	D26	COM2_RTS _N/COM2_ TX_P	Z26	GND
A27	PMC IO 54	B27	DATA 28	C27	PMC IO 53	D27	COM3_TX/ COM3_TX_ N	Z27	GIGE4_MD IO2_N
A28	PMC IO 56	B28	DATA 29	C28	PMC IO 55	D28	COM3_RTS _N/COM3_ TX_P	Z28	GND
A29	PMC IO 58	B29	DATA 30	C29	PMC IO 57	D29	COM4_TX/ COM4_TX_ N	Z29	GIGE4_MD IO3_P
A30	PMC IO 60	B30	DATA 31	C30	PMC IO 59	D30	COM4_RTS _N/COM4_ TX_P	Z30	GND

Table 3-6 P2 Connectors

P2 Connector (1st Row)		P2 Connector (2nd Row)		P2 Connector (3rd Row)		P2 Connector (4th Row)		P2 Connector (5th Row)	
Pin Name	Signal Description	Pin Name	Signal Description	Pin Name	Signal Description	Pin Name	Signal Description	Pin Name	Signal Description
A31	PMC IO 62	B31	GND	C31	PMC IO 61	D31	GND	Z31	GIGE4_MD IO3_N
A32	PMC IO 64	B32	+5V	C32	PMC IO 63	D32	+5V	Z32	GND

Table 3-7 VXS P0 Connector

Pin	Row G	Row F	Row E	Row D	Row C	Row B	Row A
1	NC	GND	P1_TX0_N	P1_TX0_P	GND	P1_RX0_N	P1_RX0_P
2	GND	P1_TX1_N	P1_TX1_P	GND	P1_RX1_N	P1_RX1_P	GND
3	NC	GND	P1_TX2_N	P1_TX2_P	GND	P1_RX2_N	P1_RX2_P
4	GND	P1_TX3_N	P1_TX3_P	GND	P1_RX3_N	P1_RX3_P	GND
5	NC	GND	SG_TX0_N	SG_TX0_P	GND	SG_RX0_N	SG_RX0_P
6	GND	NC	NC	GND	NC	NC	GND
7	GPIO0	GND	NC	NC	GND	NC	NC
8	GND	NC	NC	GND	NC	NC	GND
9	GPIO1	GND	NC	NC	GND	NC	NC
10	GND	SATA_TX_N	SATA_TX_P	GND	SATA_RX_N	SATA_RX_P	GND
11	NC	GND	SG_TX1_N	SG_TX1_P	GND	SG_RX1_N	SG_RX1_P
12	GND	P2_TX0_N	P2_TX0_P	GND	P2_RX0_N	P2_RX0_P	GND
13	NC	GND	P2_TX1_N	P2_TX1_P	GND	P2_RX1_N	P2_RX1_P
14	GND	P2_TX2_N	P2_TX2_P	GND	P2_RX2_N	P2_RX2_P	GND
15	NC	GND	P2_TX3_N	P2_TX3_P	GND	P2_RX3_N	P2_RX3_P

3.2.2.2 On-board Connectors

The on-board customized SATA connector is compatible with the MVME8100 SATA kit.

Following are the onboard connectors:

- SATA connector
- PMC connector
- Asset JTAG connector
- COP connector
- XMC connector

SATA Connector:

The on-board customized SATA connector is compatible with the Artesyn SATA kit MVME8100-HDMNTKIT4.

Table 3-8 Customized SATA Connector

Pin Name	Signal Description	Pin Name	Signal Description
1	GND	21	GND
2	GND	22	SATA POWER ENABLE
3	NC	23	NC
4	SATA TX +	24	SATA DETECT
5	NC	25	NC
6	SATA TX -	26	GND
7	GND	27	NC
8	GND	28	GND
9	GND	29	GND
10	GND	30	GND
11	NC	31	+3.3V
12	SATA RX -	32	+5V
13	NC	33	+3.3V
14	SATA RX +	34	+5V
15	GND	35	+3.3V
16	GND	36	+5V

Table 3-8 Customized SATA Connector

Pin Name	Signal Description	Pin Name	Signal Description
17	NC	37	+3.3V
18	GND	38	+5V
19	NC	39	+3.3V
20	GND	40	+5V

PMC Connectors

The MVME8100 supports two PMC sites. The connector is located on the middle portion of the board. It utilizes J14 to support PMC I/O that goes to RTM PMC.

Table 3-9 PMC J11/J21 Connector

Pin Name	Signal Description	Pin Name	Signal Description
1	JTAG TCK	33	FRAME
2	-12V	34	GND
3	GND	35	GND
4	INT A	36	IRDY
5	INT B	37	DEVSEL
6	INT C	38	+5V
7	PRESENT SIGNAL	39	PCIXCAP
8	+5V	40	LOCK
9	INT D	41	NC
10	NC	42	NC
11	GND	43	PAR
12	NC	44	GND
13	PCI CLK	45	+3.3V
14	GND	46	AD 15
15	GND	47	AD 12
16	GNT A	48	AD 11

Table 3-9 PMC J11/J21 Connector

Pin Name	Signal Description	Pin Name	Signal Description
17	REQ A	49	AD 9
18	+5V	50	+5V
19	+3.3V	51	GND
20	AD 31	52	CBE0
21	AD 28	53	AD 6
22	AD 27	54	AD 5
23	AD 25	55	AD 4
24	GND	56	GND
25	GND	57	+3.3V
26	CBE3	58	AD 3
27	AD 22	59	AD 2
28	AD 21	60	AD 1
29	AD 19	61	AD 0
30	+5V	62	+5V
31	+3.3V	63	GND
32	AD 17	64	REQ64

Table 3-10 PMC J12/J22 Connector

Pin Name	Signal Description	Pin Name	Signal Description
1	+12V	33	GND
2	JTAG TRST	34	IDSELB
3	JTAG TMS	35	TRDY
4	JTAG TDO	36	+3.3V
5	JTAG TDI	37	GND
6	GND	38	STOP
7	GND	39	PERR
8	NC	40	GND

Table 3-10 PMC J12/J22 Connector

Pin Name	Signal Description	Pin Name	Signal Description
9	NC	41	+3.3V
10	NC	42	SERR
11	BUSMODE2 (Pulled UP)	43	CBE1
12	+3.3V	44	GND
13	PCI RESET	45	AD 14
14	BUSMODE3 (PULLED DWN)	46	AD 13
15	+3.3V	47	M66EN
16	BUSMODE4 (PULLED DWN)	48	AD 10
17	NC	49	AD 8
18	GND	50	+3.3V
19	AD 30	51	AD 7
20	AD 29	52	REQB
21	GND	53	+3.3V
22	AD 26	54	GNTB
23	AD 24	55	NC
24	+3.3V	56	GND
25	IDSEL	57	NC
26	AD 23	58	EREADEY
27	+3.3V	59	GND
28	AD 28	60	RSTOUT
29	AD 18	61	ACK64
30	GND	62	+3.3V
31	AD 16	63	GND
32	CBE2	64	NC

Table 3-11 PMC J13/J23 Connectors

Pin Name	Signal Description	Pin Name	Signal Description
1	NC	33	GND
2	GND	34	AD48
3	GND	35	AD 47
4	CBE7	36	AD 52
5	CBE6	37	AD 45
6	CBE5	38	GND
7	CBE4	39	+3.3V
8	GND	40	AD 40
9	+3.3V	41	AD 43
10	PAR64	42	AD 42
11	+3.3V	43	AD 41
12	AD 62	44	GND
13	AD 61	45	GND
14	GND	46	AD 40
15	GND	47	AD 39
16	AD 60	48	AD 38
17	AD 59	49	AD 37
18	AD 58	50	GND
19	AD 57	51	GND
20	GND	52	AD 36
21	+3.3V	53	AD 35
22	AD 56	54	AD 34
23	AD 55	55	AD 33
24	AD 54	56	GND
25	AD 53	57	+3.3V
26	GND	58	AD 32
27	GND	59	NC

Table 3-11 PMC J13/J23 Connectors

Pin Name	Signal Description	Pin Name	Signal Description
28	GND	60	NC
29	AD 51	61	NC
30	AD 50	62	GND
31	AD 49	63	GND
32	GND	64	NC

Table 3-12 PMC J14 Connector

Pin Name	Signal Description	Pin Name	Signal Description
1	PMC IO 1	33	PMC IO 33
2	PMC IO 2	34	PMC IO 34
3	PMC IO 3	35	PMC IO 35
4	PMC IO 4	36	PMC IO 36
5	PMC IO 5	37	PMC IO 37
6	PMC IO 6	38	PMC IO 38
7	PMC IO 7	39	PMC IO 39
8	PMC IO 8	40	PMC IO 40
9	PMC IO 9	41	PMC IO 41
10	PMC IO 10	42	PMC IO 42
11	PMC IO 11	43	PMC IO 43
12	PMC IO 12	44	PMC IO 44
13	PMC IO 13	45	PMC IO 45
14	PMC IO 14	46	PMC IO 46
15	PMC IO 15	47	PMC IO 47
16	PMC IO 16	48	PMC IO 48
17	PMC IO 17	49	PMC IO 49
18	PMC IO 18	50	PMC IO 50
19	PMC IO 19	51	PMC IO 51

Table 3-12 PMC J14 Connector

20	PMC IO 20	52	PMC IO 52
21	PMC IO 21	53	PMC IO 53
22	PMC IO 22	54	PMC IO 54
23	PMC IO 23	55	PMC IO 55
24	PMC IO 24	56	PMC IO 56
25	PMC IO 25	57	PMC IO 57
26	PMC IO 26	58	PMC IO 58
27	PMC IO 27	59	PMC IO 59
28	PMC IO 28	60	PMC IO 60
29	PMC IO 29	61	PMC IO 61
30	PMC IO 30	62	PMC IO 62
31	PMC IO 31	63	PMC IO 63
32	PMC IO 32	64	PMC IO 64

Asset JTAG Connector

The MVME8100 contains a 20-pin 0.1" header for an Asset JTAG header. The pinout for the header is given in the following table.

Table 3-13 Asset JTAG Header Pin Assignment

PIN Number	Description	PIN Number	Description
1	TCK	2	ASSET_PRSENT_L (GND on cable)
3	TDO	4	GND
5	TMS	6	GND
7	TRST_L	8	GND
9	TDI	10	GND
11	No Pin Key	12	Reserved - NC
13	GND	14	Reserved - NC
15	GND	16	Reserved - NC

Table 3-13 Asset JTAG Header Pin Assignment

PIN Number	Description	PIN Number	Description
17	GND	18	Reserved - NC
19	GND	20	Reserved - NC

XMC Connector

MVME8100 supports two XMC sites. The board only supports J15 for XMC site 1 and J25 for XMC site 2.

Table 3-14 XMC Connectors

XJ1/2 (ROW A)		XJ1/2 (ROW B)		XJ1/2 (ROW C)		XJ1/2 (ROW D)		XJ1/2 (ROW E)		XJ1/2 (ROW F)	
Pin No	Signal Description	Pin No	Signal Description	Pin No	Signal Description	Pin No	Signal Description	Pin No	Signal Description	Pin No	Signal Description
1	RX0 +	1	RX0 -	1	+3.3V	1	RX0 +	1	RX1 -	1	+3.3V
2	GND	2	GND	2	JTAG TRST	2	GND	2	GND	2	HRESET
3	NC	3	NC	3	+3.3V	3	NC	3	NC	3	+3.3V
4	GND	4	GND	4	JTAG TCK	4	GND	4	GND	4	MRSTO (PULLED UP)
5	NC	5	NC	5	+3.3V	5	NC	5	NC	5	+3.3V
6	GND	6	GND	6	JTAG TMS	6	GND	6	GND	6	+12V
7	NC	7	NC	7	+3.3V	7	NC	7	NC	7	+3.3V
8	GND	8	GND	8	JTAG TMS	8	GND	8	GND	8	-12V
9	NC	9	NC	9	NC	9	NC	9	NC	9	+3.3V
10	GND	10	GND	10	JTAG TDO	10	GND	10	GND	10	GA 0
11	TX0	11	TX0 -	11	BIST (PULLED UP)	11	TX1 +	11	TX1 -	11	+3.3V
12	GND	12	GND	12	GA 1	12	GND	12	GND	12	PRESENT
13	NC	13	NC	13	NC	13	NC	13	NC	13	+3.3V
14	GND	14	GND	14	GA 2	14	GND	14	GND	14	I2C DATA
15	NC	15	NC	15	NC	15	NC	15	NC	15	+3.3V

Table 3-14 XMC Connectors

XJ1/2 (ROW A)		XJ1/2 (ROW B)		XJ1/2 (ROW C)		XJ1/2 (ROW D)		XJ1/2 (ROW E)		XJ1/2 (ROW F)	
Pin No	Signal Description	Pin No	Signal Description	Pin No	Signal Description	Pin No	Signal Description	Pin No	Signal Description	Pin No	Signal Description
16	GND	16	GND	16	MVMRO (PULLED DOWN)	16	GND	16	GND	16	I2C CLOCK
17	NC	17	NC	17	NC	17	NC	17	NC	17	NC
18	GND	18	GND	18	NC	18	GND	18	GND	18	NC
19	CLK +	19	CLK -	19	NC	19	NC	19	ROOT0 (PULLED UP)	19	NC

Functional Description

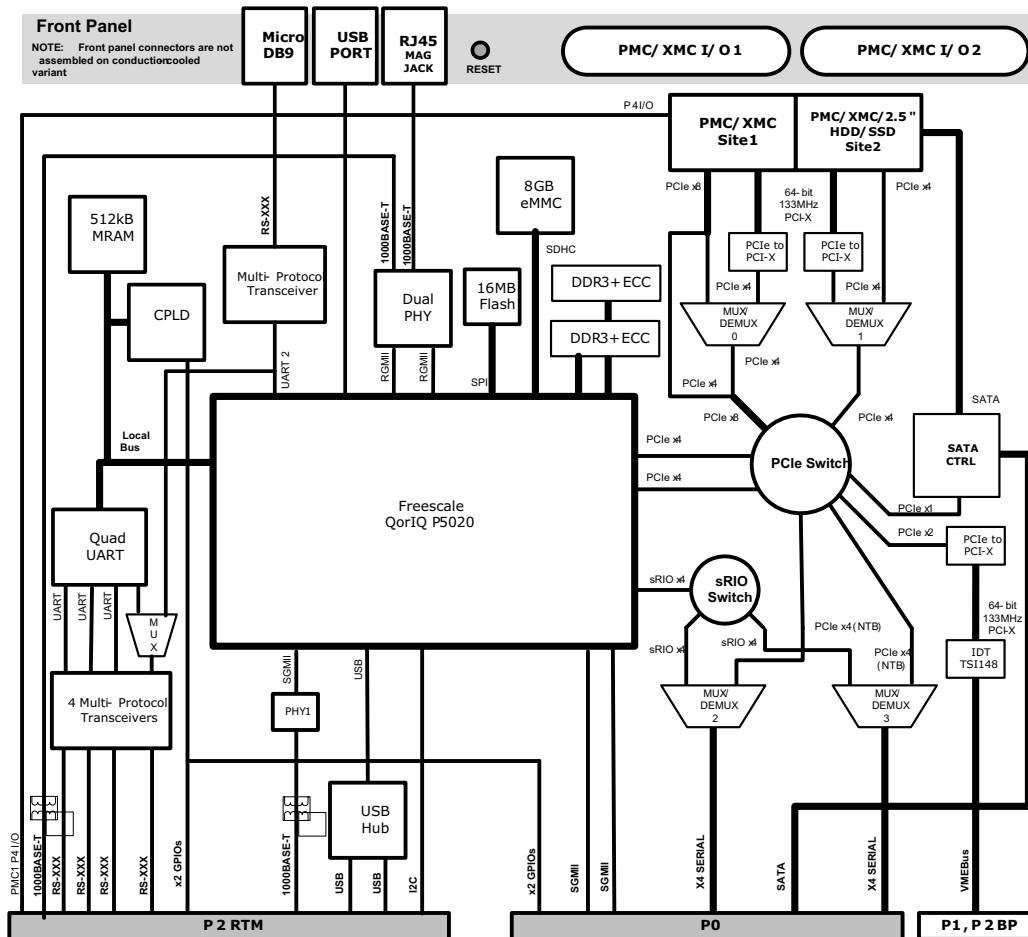
4.1 Overview

The MVME8100 Single Board Computer is a 6U VME/VXS board based on the Freescale QorIQ P5020 processor. This section describes the features of MVME8100.

4.2 Block Diagram

Figure 4-1 illustrates the MVME8100 architecture.

Figure 4-1 Block Diagram



4.3 Processor

The P5020 QorIQ processor combines two Power architecture processor cores with high-performance data path acceleration logic and network, and peripheral bus interfaces required for networking, telecom/datacom, wireless infrastructure and aerospace applications.

This device can be used for combined control, data path and application layer processing in routers, switches, base station controllers, and general-purpose embedded computing. Its high level of integration offers significant performance benefits compared to multiple discrete devices while also greatly simplifies the board design.

The MVME8100 board ENP1 version is designed to use the 2.0 GHz core processor version while the ENP4 version uses the 1.8 GHz processor.

For more information, refer P5020 QorIQ Integrated Multicore Communications Processor Family Reference Manual.

4.4 System Memory

The MVME8100 supports four GB DDR3 ECC memory using two banks of 2Gb memory devices.

The memory devices are soldered-down and not modular solution using DIMM sockets. The supported data rate is 1333MT/s. The memory is evenly-distributed across both memory channels (e.g. memory-capacity requirement is 4GB, place 2GB of memory on each channel).

4.5 Timers

This section describes the timer functions implemented on MVME8100.

4.5.1 Real Time Clock

The MVME8100 implements an Real Time Clock (RTC) to maintain seconds, minutes, hours, day, date, month, and year accurately. It includes a 32.768 KHZ crystal, DS1337 RTC, and back up power. For the ENP1 version of the MVME8100, a battery is used for the RTC back up power. For the ENP4 version, a 3.3V regulator powered from the VME backplane +5V_STDBY voltage is used for back up power. The DS1337 has an interrupt output (INTA) which can be programmed to assert a processor IRQ on a time/day/date match. The DS1337 also has a 32.768 KHz clock output (SQW) which is used to drive the P5020 RTC input signal.

The RTC internal oscillator has been disabled before the board was shipped from the factory. Use the following process to turn on the RTC oscillator from Uboot:

```
MVME8100 => i2c mm 0x68 e.1
0000000e: 98 ? 18
0000000f: 80 ? n
```

To set the date, use the following uboot command:

```
MVME8100 =>date [MMDDhhmm[[CC]YY][.ss]]
```

4.5.2 P5020 Internal Timers

The P5020 provides a total of eight global timers; it is divided into two groups, group A and group B. Each group has four timers. Each timer has four individual configuration register. However, these two groups of timers cannot be cascaded together.

4.5.3 Watchdog Timers

The CPLD has two watchdogs timers, the Initial Hardware Watchdog (IWD) and the OS Watchdog (OSWD).

The Initial Hardware Watchdog is used to guard loading of U-Boot and to prevent board hanging up. U-Boot has to service IWD before timeout, or IWD will request Power-On Reset. Following a board reset, the board will try to boot from the U-Boot Flash selected by the configuration switches. If IWD is not serviced in time by U-Boot, then following the IWD reset, the board will attempt to boot from the alternate SPI1 U-Boot Flash device.

The OS Watchdog (OSWD) is used to guard loading of the operating system. The OS has to service OSWD before timeout or OSWD will request a hard reset sequence to reset the board.



If IWD is not serviced after switching over to the SPI1 U-Boot Flash, board will infinitely try to boot to SPI1 U-Boot Flash.

By default, U-Boot will disable both the IWD and the OSWD.

The configuration switch S2-1 is used to enable or disable both watchdogs. By default, the watchdogs are disabled.

4.5.3.1 Initial Hardware Watchdog

Initial Hardware Watchdog (IWD) starts after reset deassertion. This watchdog has to be serviced within 8s after a reset deassertion, otherwise a IWD reset will be requested.

The Initial Hardware Watchdog is serviced by writing 0xEEA1 to CPLD Command/Status Register.

4.5.3.2 OS Watchdog

The OS Watchdog (OSWD) is not armed after reset. It is enabled right after the IWD is disabled. The OSWD timeout is set to 108s. If the timer terminates, the OSWD reset sequence will be initiated.

OSWD is serviced and disabled by writing 0xBBC2 to CPLD Command/Status Register.

4.5.4 CPLD Tick Timer

The MVME8100 is designed to provide three independent 32-bit timers. These timers are implemented in the CPLD which provides the fully programmable registers required for these timers.

4.6 Ethernet Interfaces

The P5020 has five dTSEC controllers. The controllers can be configured to implement RGMII, GMII, or SGMII interfaces to external Ethernet transceivers.

The MVME8100 utilizes dTSEC4 for a dedicated front panel 10/100/1000BASE-T interface and dTSEC5 for a 10/100/1000BASE-T interface to the RTM via P2. A Broadcom BCM5482 dual transceiver provides the RGMII -> 10/100/1000BASE-T interfaces. A second 10/100/1000BASE-T interface to the RTM through P2 is provided using dTSEC3 in SGMII mode. A Broadcom BCM54616S transceiver provides the SGMII -> 10/100/1000BASE-T interface. The registers of these transceivers can be accessed via the P5020's two-wire Ethernet Management interface.

The front panel RJ45 connector has integrated speed and activity status indicator LED's. Similar to the front panel Ethernet, the RJ45 connectors found in the RTM have integrated speed and activity status indicator LED's. Isolation transformers are provided on-board for each of the RTM ports.

The MVME8100 utilizes dTSEC1 and dTSEC2 in SGMII mode for two additional 1000Base-BX Ethernet ports to P0.

4.7 SPI Interface

Firmware boot Flash resides on the P5020 eSPI bus interface.

4.7.1 SPI Flash Memory

The P5020 contains two Eight MB serial flash devices. These devices contain the 512 bits of the Reset Configuration Word, the boot firmware image (U-boot), and the ENV environment variables.

4.7.2 Firmware Redundancy

The MVME8100 utilizes two separate Eight MB boot devices in order to provide boot firmware redundancy. The P5020 SPI device controller uses Chip Select 0 as the boot device, so CPLD logic is used on the MVME8100 in order to swap the chip select to the boot devices. The chip select control is based upon the configuration switch S5-1.

At power-up, the selection of the SPI boot device is strictly based upon the switch S5-1 setting. The selected SPI device must contain a boot image. The MVME8100 supports automatic SPI FLASH fail-over. If booting on one device is not successful, then the watchdog will trigger a board reset and the CPLD logic automatically toggle chip selects, and tries to boot on the other device.

4.8 MRAM

The MVME8100 includes one MR2A16AVYS35 512 KB MRAM device to provide a non-volatile memory, that has virtually unlimited writes (100 trillion), fast access and ten years data retention without power. The MRAM is organized as 256Kx16 and accessible through the P5020 local bus.

4.9 eMMC

The MVME8100 contains a soldered down 8GB eMMC device connected to the P5020 eSDHC interface. The eSDHC interface operates in four bit MMC mode and supports up to 200Mbps data transfer for MMC card using four parallel data lines.

4.10 Processor Console Port

The MVME8100 utilizes P5020 UART1 port for the processor console interface. This console interface can be routed to the front panel or the P2 connector using configuration switches. The front panel port can be configured for RS-232 or RS-422/RS-485 modes. RS-232 mode supports RX, TX, RTS and CTS signals. Only four wire full duplex RX/TX is supported in RS422/485 mode. The signaling mode is selected through on board configuration switches. The default baud rate on the front panel serial is 9600 baud.

The physical front panel console connector is a male micro-min DB-9. A male- to -male micro-mini DB9 to DB9 adapter cable is available under Artesyn Part Number SERIAL MINI-D (30-W2400E01A).

4.11 Rear UART Ports

The MVME8100 provides four asynchronous serial UART interfaces to the P2 RTM connector by utilizing Exar's ST16C554 quad UART. The QUART features 16 bytes of transmit and receive FIFO's, it has a selectable receive FIFO trigger levels and data rates of up to 1.5Mbps. Each UART has a set of registers that provide the user with operating status and control. The QUART is a 8 bit device connected to the P5020 through the local bus controller. QUART port A is multiplexed with the P5020 UART1 console port, so that the console port can be routed to the RTM COM1 port. The mux is controlled using configuration switches on S2.

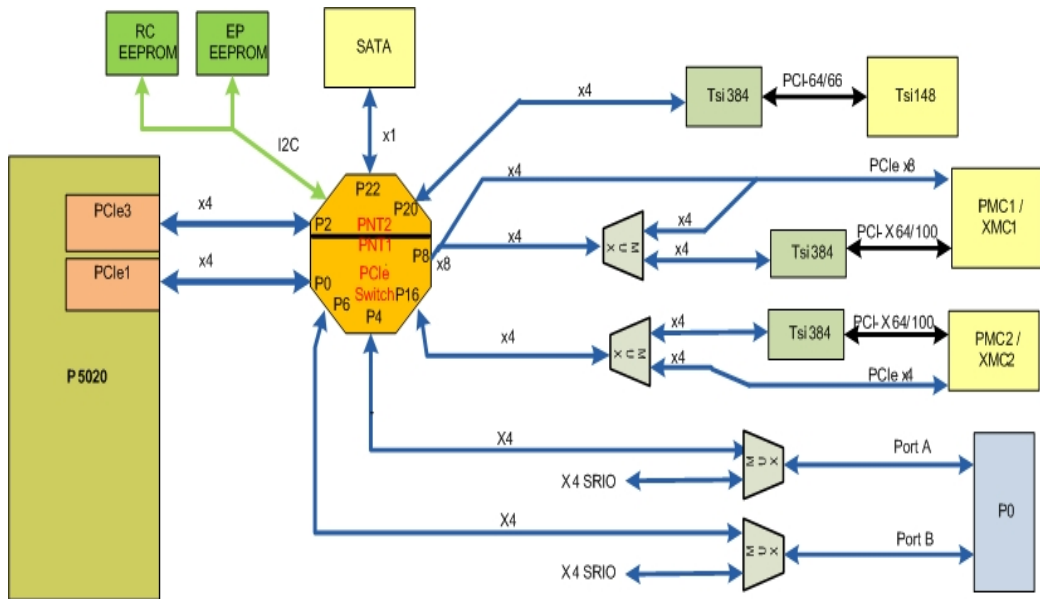
The four ports can be configured for RS-232 or RS-422/RS-485 modes. RS-232 mode supports RX, TX, RTS and CTS signals. Only four wire full duplex RX/TX is supported in RS422/485 mode. The signaling mode is selected through on board configuration switches on S2.

4.12 PCIe Ports

The MVME8100 provides multiple PCI Express ports. The P5020 is configured to use two x4 PCIe controllers (#1 and #3) on the MVME8100. Both controllers are configured to operate at Gen 1 data rate (2.5 Gbaud). These ports are routed to an IDT 32NT24AG2 PCIe switch for expansion of the PCIe ports. The IDT switch is a 32 lane Gen 2 device and can support up to 24 ports, 8 of which are capable of NT function. Each port of the switch is configured to operate at Gen 1 data rate. The configuration of the ports and the partitioning of the switch into a single or multiple domains is controlled by an I2C eeprom connected to the PCIe switch master SMBus and loaded into the switch following reset.

The board provides two separate eeproms so that separate configuration data can be maintained for the MVME8100 operating as a root complex or as an end point on the P0 connector ports. The selection of the root complex or end point eeprom for loading the configuration data after reset is determined by the root complex configuration switch S4-2 (see [S4 Switch on page 38](#).). The eeproms can be reprogrammed from the processor using the I2C master interface in the IDT device. A swap bit in CPLD control register can be used to temporarily swap the eeprom device addressing so that the alternate eeprom can be reprogrammed. A diagram of the PCIe port configuration is shown in the figure below.

Figure 4-2 PCIe Ports



4.13 SRIO Ports

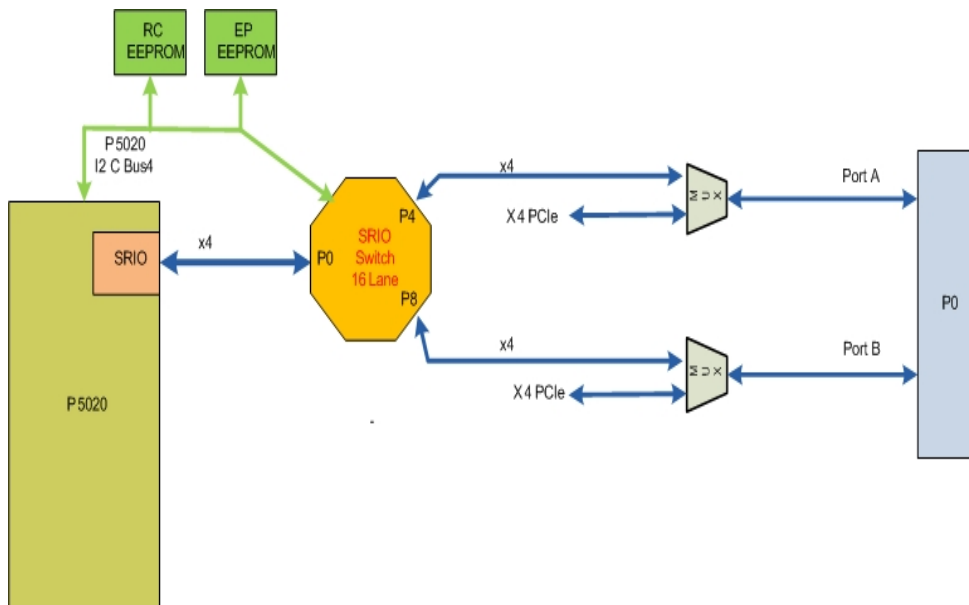
The MVME8100 also provides multiple SRIO ports. The P5020 provides a single x4 SRIO configured for 2.5 Gbaud data rate. This port is routed to an IDT 80HCPS1616 SRIO switch for expansion of the SRIO ports. The SRIO switch supports multiple lane speeds including 1.25, 2.5, 3.125 and 5.0 Gbaud. The MVME8100 provides two x4 SRIO ports which may be routed to the P0 connector through a high speed mux. The selection of SRIO or PCIe ports to P0 is controlled by the S2-8 configuration switch (see [S2 Switch on page 35](#)). The configuration of the SRIO switch ports is controlled by an I2C eeprom connected to the SRIO switch I2C bus and loaded into the switch following reset. The board provides two separate eeproms so that separate configuration data can be maintained for the MVME8100 operating as a root complex or as an end point on the P0 ports. The selection of the root complex or end point eeprom for

loading the configuration data after reset is determined by the root complex configuration switch S4-2 (see [S4 Switch on page 38](#)). The eeproms can be reprogrammed over the processor I2C bus 4 interface. The eeprom device addresses are listed in section [I2C Devices on page 82](#). A diagram of the SRIO port topology is shown in the figure below.



The 80HCPS1616 SRIO switch does not support auto baud rate discovery. The switch configuration EEPROMs must program the P0 fabric ports to match the SRIO baud rate of the system. The default baud rate for the P0 fabric ports is 2.5 Gbaud.

Figure 4-3 SRIO Bus Topology



4.14 PMC/XMC Sites

The MVME8100 provides two PMC/XMC sites. Each PMC/XMC site will accept either a PMC or an XMC add-on card. For a given PMC/XMC site, only an XMC or a PMC may be populated at any given time, as they occupy the same physical space on the PCB. Combination of PMC/XMC cards are not supported by MVME8100. The PMC/XMC1 site provides rear PMC I/O.

The PMC/XMC sites are fully compliant with the following:

- VITA 39 -PCI-X for PMC
- VITA 35-2000 for PMC P4 to VME P2 Connection (PMC/XMC1 site only)
- PCI Rev 2.2 for PCI Local Bus Specification
- PCI-X PT 2.0 for PCI-X Protocol Addendum to the PCI Local Bus Specs
- IEEE Standard P1386-2001 for Standard for Common Mezzanine Card Family
- IEEE Standard P1386.1-2001 for Standard Physical and Environmental Layer for PCI Mezzanine Card.
- VITA 42 for XMC
- VITA 42.3, PCIe for XMC

PMC/XMC sites are keyed for 3.3V PMC signaling.

MVME8100 provides a x8 PCI Express interface link for PMC/XMC1 and x4 PCI Express interface link for PMC/XMC2. It is designed such that same PCI Express interface is used for either the XMC or the PCIe to PCI-X bridge required for a PMC. This is made possible by using Pericom PI3PCIE3412 PCIe mux devices. The PCIe Mux at both sites is controlled by the CPLD. The CPLD detects the presence signal provided by the XMC or PMC board and it will be used to configure the routing of PCIe Mux accordingly.

4.14.1 PMC Add-on Card

The MVME8100 supports up to two PMC cards. PCI-X operation to each site is provided using a separate IDT TSI384 PCIe to PCI-X bridge for each site. Each Tsi384 can support up to 8.5Gbps (64bits x 133 Mhz). An onboard switch will configure the TSI384 to run on either 100 MHz or 133 MHz. The default is 133 MHz.

The MVME8100 supports multi-function PMCs and Processor PMC's (PrPMCs). The PCI signaling voltage (VIO) for the site is 3.3V as required by the Tundra Tsi384 and is keyed as such. The power budget allocated to 3.3V is 16.5W (max) for either PMC or PrPMC. The PMC site has two IDSELs, two REQ/GNT pairs, and EREADY to support PrPMC modules as defined by VITA39.

4.14.2 XMC Add-on Card

XMC add-on cards are required to operate off of +5V or +12V (from carrier to XMC). The MVME8100 provides +5V to the XMC VPWR (Variable Power) pins. The MVME8100 does not provide +12V to the XMC VPWR pins. Voltage tolerances for VPWR and all carrier supplied voltage (+3.3V, +12V, -12V) are defined by the base XMC standard.

4.15 SATA interface

The MVME8100 is designed to support an optional 2.5 inch SATA HDD/SDD in PMC/XMC site 2. The heat frame has mounting holes to support the 2.5" SSD/HDD on board. The connector interface to the MVME8100 board is compatible with the Artesyn SATA mounting kit MVME8100-HDMNTKIT4, which contains a SATA adapter board, screws and mounting brackets. The SATA adapter board provides a standard SATA connector to support horizontal mounting of the HDD/SSD.

MVME8100 utilizes Marvell's 88SE9125B1 SATA controller. This is a PCI Express 2.0 to dual SATA 3.0 Host Bus Adapter. It employs the latest SATA PHY technology, operating at 1.5Gbps or 3.0Gbps.

4.16 VME Support

The MVME8100 is designed to comply with VME ANSI/VITA 1.5-2003, 2eSST. The MVME8100 supports most of the addressing and data transfer modes defined by the VME64, VME64x and 2eSST specifications. The MVME8100 can operate in System Controller (SCON) mode or in Non-SCON mode. This is determined by on board switch settings on S4.

4.16.1 Tsi148 VME Controller

The Tsi148 provides the required VME64, VME64X and 2eSST functions. TI SN74VMEH22501 transceivers buffer the VME signals between Tsi148 and the VME backplane. Refer to the *IDT Tsi148 User's Manual* for additional details and programming information.

4.16.2 Tsi384 PCIe to PCI/PCI-X Bridge

The PCIe to PCI/PCI-X Bridge function required to interface to the Tsi148 is provided by the Tundra Tsi384 device. The Tsi384 is responsible for bridging bi-directional traffic between the PCIe switch and the Tundra Tsi148. Per ANSI/VITA 1.5-2003, the theoretical maximum transfer rate for a 6U VME card in 2eSST mode is 320MBps, or 2.62 Gbps.

4.17 USB

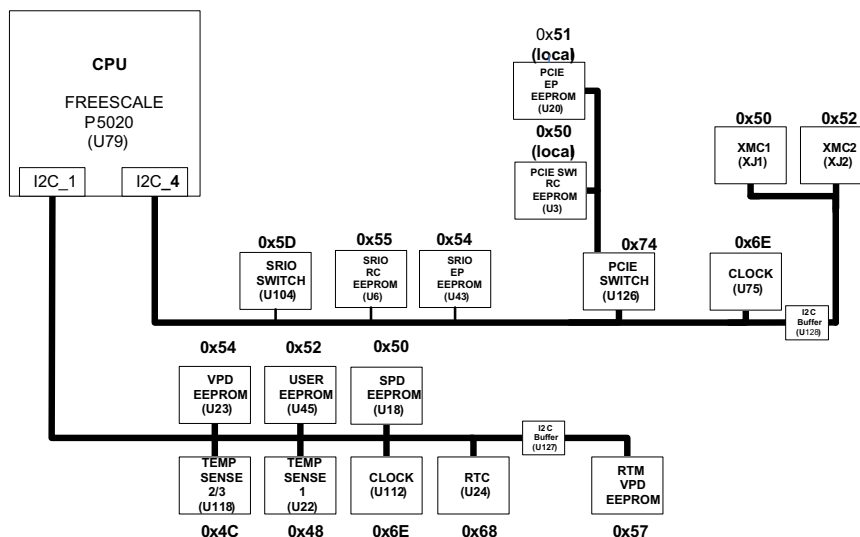
The P5020 provides two USB 2.0 controllers with integrated PHYs. The MVME8100 routes USB port 1 to the front panel to an upright USB Type A receptacle. The DC power for the front panel USB port is supplied through Micrel's MIC2076 power switch which provides soft, current limiting, over current detection and power enable.

The P5020 USB port 2 is routed to a USB2512 hub device which provides two additional downstream USB 2.0 ports. The two additional downstream ports are routed to the P2 connector for use on the RTM.

4.18 I2C Devices

The P5020 provides four I2C controllers, but only controller 1 and controller 4 are used. The I2C ports are connected to multiple devices such as VPD, SPD, User EEPROMs, switch configuration EEPROMs, RTC, temperature sensors, RTM EEPROM, XMC EEPROMS, and clock devices. The RTM and XMC EEPROM addresses are configured such that they do not have an address conflict with other on board device address. The I2C busses and device addresses are shown in [Figure 4-4](#). For more information, refer *MVME8100 Programmer's Reference*.

Figure 4-4 I2C Busses



4.19 Reset/Control CPLD

The MVME8100 uses a Lattice LCMXO2280C CPLD to provide reset, power up sequencing, timers, miscellaneous board logic, and status/control registers accessible through the P5020 LBC interface. The CPLD uses early 3.3V power from the +5V backplane and can be programmed through JTAG interface pins through the JTAG connector. It uses a 1.8 MHz oscillator for logic control.

The CPLD provides the following functions:

- Power control and fault detection
- Reset sequence and reset management
- Status and Control registers
- Miscellaneous control logics
- Watchdog timer
- 32-bit Tick Timers
- Clock generator
- Switch decoder and LED controller

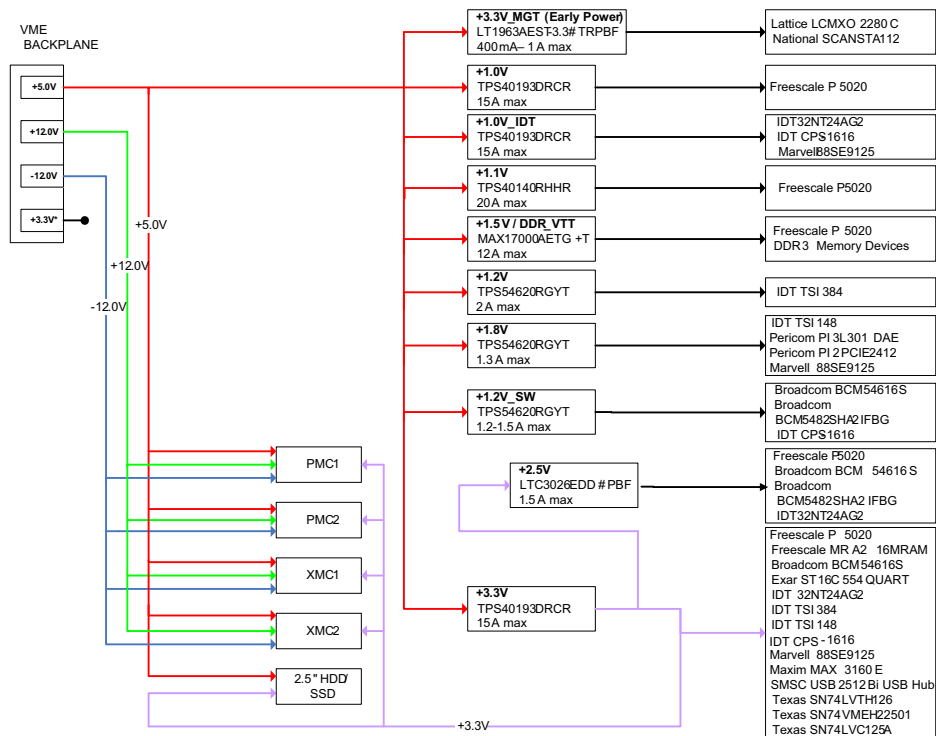
4.20 Power Management

The 5 volt coming from the back plane is utilized to derive all on-board voltage rails. To provide the required voltage sequencing, each voltage rail is controlled by the CPLD through enable pin of each regulator and the output is being monitored by CPLD through each regulator power good signal. If one voltage rail fails, the CPLD will disable all of the regulators and the only way to restart the board is by power cycling the chassis 5 volt power.

4.20.1 Power Distribution Structure

Figure 4-5 displays the MVME8100 power distribution structure.

Figure 4-5 Power Distribution



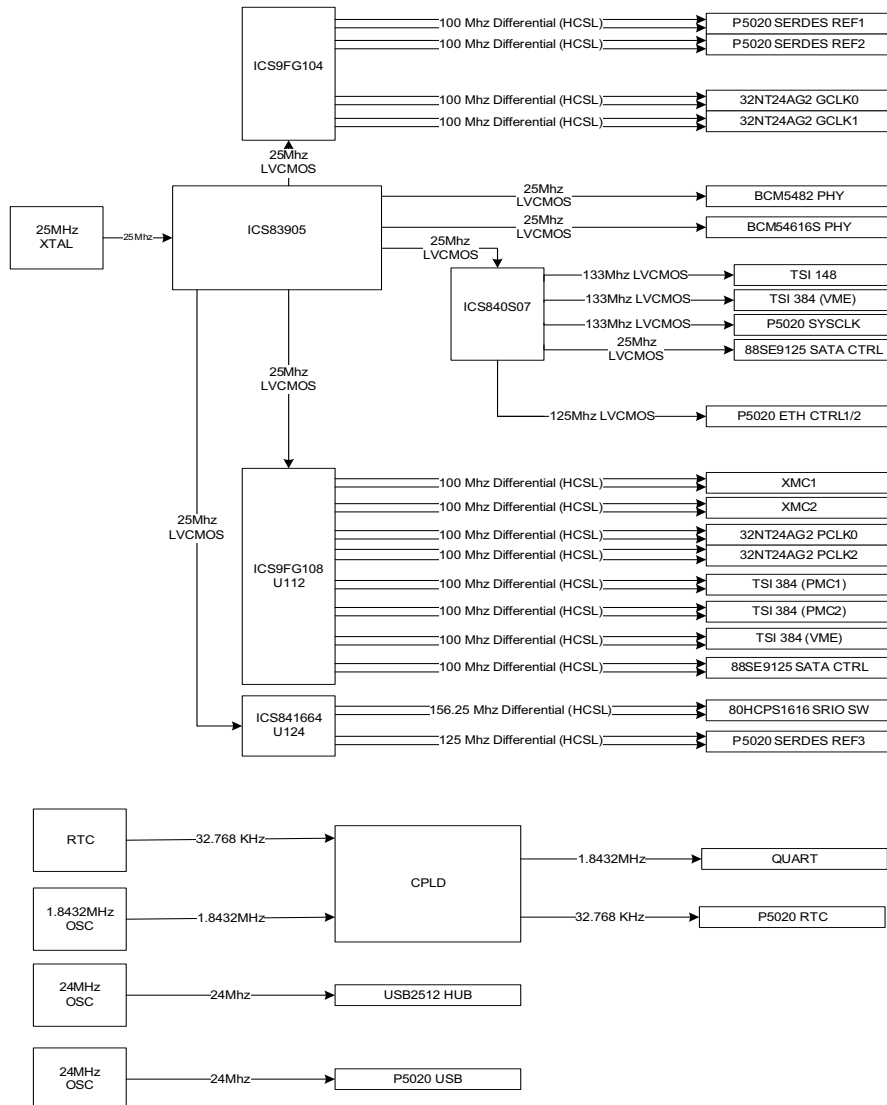
4.20.2 Power Sequence Requirements

The CPLD power sequence timing is designed to support all the MVME8100 devices supply voltage sequencing requirements.

4.21 Clock Structure

Figure 4-7 shows the clock tree implementation for the MVME8100.

Figure 4-6 Clock Structure

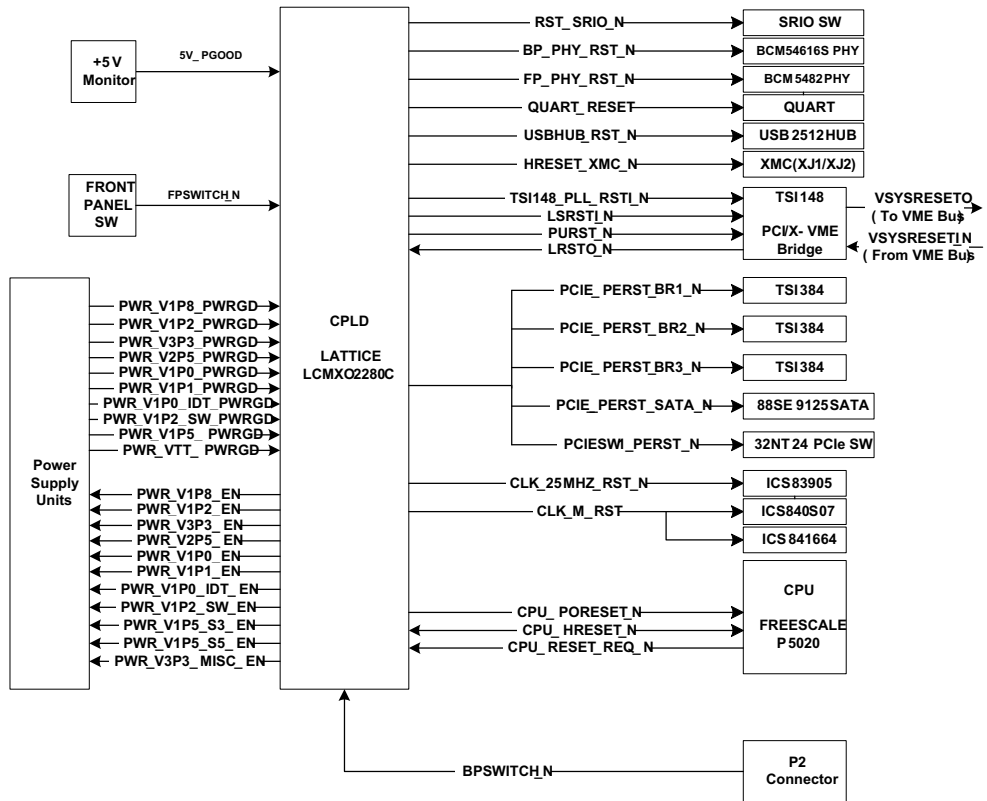


4.22 Reset Structure

The MVME8100 reset begins after the power up sequence is completed. A board reset can also be initiated using the front panel reset switch, the RTM reset switch (through P2) or under software control through the processor Reset Request.

Figure 4-7 illustrates the reset control structure.

Figure 4-7 Reset Control Diagram



4.23 Interrupt Controller Assignments

The following table shows the external interrupts connected to the P5020:

Table 4-1 P5020 External Interrupt Assignments

P5020 Interrupt	Interrupt Source	Description
IRQ0	None	Reserved
IRQ1	BCM5482 INT1	BCM5482 PHY interrupt 1 from LED_P1[2] pin
IRQ2	BCM5482 INT2	BCM5482 PHY interrupt 2 from LED_P2[2] pin
IRQ3/GPIO21	QUART_IRQ0	Quart Interrupt INTA
IRQ4/GPIO22	QUART_IRQ1	Quart Interrupt INTB
IRQ5/GPIO23	QUART_IRQ2	Quart Interrupt INTC
IRQ6/GPIO24	QUART_IRQ3	Quart Interrupt INTD
IRQ7/GPIO25	CPLD_TEMP_INT_L	Board Temperature interrupt (routed through CPLD)
IRQ8/GPIO26	CPLD_TIMER_INT_L	CPLD Internal Timers and Abort IRQ
IRQ9/GPIO27	BCM54616S INT	BCM54616S PHY interrupt from LED4 pin.
IRQ10/GPIO28	SRIO_IRQ_INT_L	80HCPS1616 SRIO IRQ_N pin
IRQ11/GPIO29	RTC_INT_L	RTC interrupt (routed through CPLD)

4.24 GPIO Electrical Characteristics

The four GPIO signals routed to the P0 and P2 connectors have the following electrical characteristics:

Table 4-2 GPIO DC Electrical Characteristics

V_{IL}		V_{IH}		V_{OL} Max.(V)	V_{OH} Min.(V)	I_{OL} (mA)	I_{OH} (mA)
Min.(V)	Max.(V)	Min.(V)	Max.(V)				
-0.3	0.8	2.0	3.6	0.4	2.9	4	4
				0.2	3.1	0.1	0.1

Table 4-3 GPIO Pull-Down Characteristics

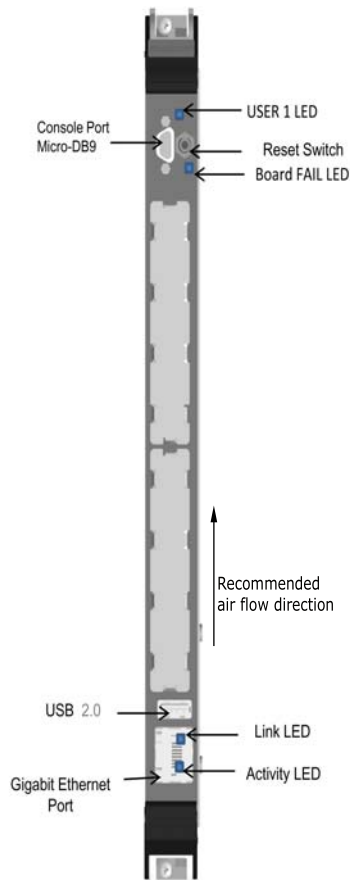
Parameter	Condition	Min.	Max	Units
I/O Active Pull-down Current	$V_{IL}(\text{Max}) \leq V_{IN} \leq V_{IH}(\text{Max})$	30	150	μA

4.25 Thermal Management

The MVME8100 provides three on-board temperature sensors using an ADT7461 dual temperature sensor and a TMP112A temperature sensor. The ADT7461 internal temperature sensor provides the temperature at the board edge on the CPU side of the board. The ADT7461 remote temperature sensor measures the CPU temperature. The ADT7461 can measure negative temperatures down to -64C with +/- 1C accuracy on the remote sensor and +/- 3C accuracy on the internal sensor. The ADT7461 registers can be used to configure the low temperature limit and high temperature limit for the local sensor as well as for the remote sensor. An interrupt can be generated if limits are exceeded. The TMP112A temperature sensor is used to measure the temperature at the board edge opposite from the CPU. Since the airflow direction can be different in some VME chassis, either temperature sensor can be used to get a measure of the board inlet air temperature, depending on the air flow direction.

However, to maintain proper CPU temperature, the recommended air flow direction is to enter the board from the CPU side, that is, the air should flow in the direction from PMC/XMC site 1 to PMC/XMC Site 2.

Figure 4-8 Thermal Management



Boot System

5.1 Overview

The MVME8100 uses Das U-Boot, a boot loader software based on the GNU Public License. It boots the blade and is the first software to be executed after the system is powered on.

Its main functions are:

- Initialize the hardware
- Pass boot parameters to the Linux kernel
- Start the Linux kernel
- Update Linux kernel and U-Boot images

This section describes U-Boot features and procedures that are specific to the MVME8100. For general information on U-Boot, see <http://www.denx.de/wiki/UBoot/WebHome>.

5.2 Accessing U-Boot

1. Connect the board to a computer with a serial interface connector and a terminal emulation software running on it. The serial connector of the board is found on the face plate.
2. Configure the terminal software to use the access parameters that are specified in U-Boot. By default, the access parameters are as follows:
 - Baud rate: 9600
 - PC ANSI
 - 8 data bits
 - No parity
 - 1 stop bit



These serial access parameters are the default values. These can be changed from within the U-Boot. For details, refer to the U-Boot documentation.

3. Boot the MVME8100.
4. When prompted, press the "Ctrl/C" key.

U-Boot aborts the boot sequence and enters into a command line interface mode.



Enter the command **setenv bootdelay -1; saveenv** to disable the U-Boot auto-boot feature and let the U-Boot directly enter the command line interface after the next reboot/power up.

5.3 Boot Options

5.3.1 Booting from a Network

In this mode, U-Boot downloads and boots the Linux kernel from an external TFTP server and mounts a root file system located on a network server.

1. Make sure that the `kernel`, `dtb`, and `ramdisk` are accessible to the board from the TFTP server.
2. Configure U-Boot environment variables:

```
setenv ipaddr <IP address of MVME8100>  
setenv serverip <IP address of TFTP server>  
setenv gatewayip <gateway IP>  
setenv netmask <netmask>  
setenv bootargs 'root=/dev/ram rw console=ttyS0,9600n8  
ramdisk_size=700000 cache-sram-size=0x10000'  
saveenv
```
3. Transfer the files through the TFTP from the server to the local memory.

```
tftp 1000000 <kernel_image>  
tftp 2000000 <ramdisk>  
tftp f00000 <kernel dtb>
```
4. Boot the Linux from the memory.

```
bootm 1000000 2000000 f00000
```

5.3.2 Booting from an Optional SATA Drive

1. Make sure that the kernel, dtb, and ramdisk are saved in the SATA drive with ext2 partition.
2. Configure U-Boot environment variable:

```
setenv File_uImage <kernel_image>
setenv File_dtb <kernel dtb>
setenv File_ramdisk <ramdisk>
saveenv
```
3. Copy the files from the SATA drive to the memory:

```
# option: scsi - interface, 0:1 - device 0 partition 1
ext2load scsi 0:1 1000000 $File_uImage
ext2load scsi 0:1 2000000 $File_ramdisk
ext2load scsi 0:1 f00000 $File_dtb
```
4. Boot the Linux in memory.

```
bootm 1000000 2000000 f00000
```

5.3.3 Booting from a USB Drive

1. Make sure that the kernel, dtb, and ramdisk are saved in the USB drive with FAT partition.
2. Configure the U-Boot environment variable:

```
setenv File_uImage <kernel_image>
setenv File_dtb <kernel dtb>
setenv File_ramdisk <ramdisk>
saveenv
```
3. Initialize USB drive:

```
usb start
```
4. Load the files from the USB drive to the memory:

```
# option: usb - interface, 0:1 - device 0 partition 1
fatload usb 0:1 1000000 $File_uImage
fatload usb 0:1 2000000 $File_ramdisk
fatload usb 0:1 f00000 $File_dtb
```
5. Boot the Linux in memory:

```
bootm 1000000 2000000 f00000
```

5.3.4 Booting from eMMC

1. Make sure that the kernel, dtb, and ramdisk are saved in the onboard eMMC device with FAT partition.
2. Configure the U-Boot environment variable:

```
setenv File_uImage <kernel_image>
setenv File_dtb <kernel dtb>
setenv File_ramdisk <ramdisk>
saveenv
```
3. Initialize eMMC

```
mmcinfo
```
4. Load the files from the eMMC to the memory:

```
# option: mmc - interface, 0:1 - device 0 partition 1
fatload mmc 0:1 1000000 $File_uImage
fatload mmc 0:1 2000000 $File_ramdisk
fatload mmc 0:1 f00000 $File_dtb
```
5. Boot the Linux in memory:

```
bootm 1000000 2000000 f00000
```

5.3.5 Booting VxWorks Through the Network

In this mode, the U-Boot downloads and boots VxWorks from an external TFTP server.

1. Make sure that the VxWorks image is accessible by the board from the TFTP server.
2. Configure U-Boot environment variables:

```
setenv ipaddr <IP address of MVME8100>
setenv serverip <IP address of TFTP server>
setenv gatewayip <gateway IP>
setenv netmask <netmask>
setenv vxboot 'tftpboot $vxbootfile && setenv bootargs
$vxbootargs && bootvx'
setenv vxbootfile <VxWorks_image>
setenv vxbootargs 'dtsec(3,0)<IP address of TFTP server>:VxWorks
h=<IP address of TFTP server> e=<IP address of MVME8100>:ffffff00
b=<unused IP> u=vxworks pw=vxworks f=0x80'
saveenv
```

3. TFTP the files from the server to local memory, then boot:
run vxboot

5.4 MVME8100 Specific U-Boot Commands

Table 5-1 MVME8100 Specific U-Boot Commands

Command	Description
base	Print or set address offset
bdinfo	Print board info structure
boot	Boot default, i.e., run 'bootcmd'
bootd	Boot default, i.e., run 'bootcmd'
bootelf	Boot from an ELF image in memory
bootm	Boot application image from memory
bootp	Boot image through network using BOOTP/TFTP protocol
bootvx	Boot VxWorks from an ELF image
cmp	Memory compare
coninfo	Print console devices and information
cp	Memory copy
cpu	Multiprocessor CPU boot manipulation and release
crc32	Checksum calculation
date	Get/set/reset date & time
diags	Runs POST diags
echo	Echo args to console
exit	Exit script
ext2load	Load binary file from a Ext2 file system
ext2ls	List files in a directory (default /)
fatinfo	Print information about file system
fatload	Load binary file from a DOS file system

Table 5-1 MVME8100 Specific U-Boot Commands (continued)

Command	Description
fatls	List files in a directory (default /)
fdt	Flattened device tree utility commands
go	Start application at address 'addr'
help	Print online help
i2c	I2C sub-system
iminfo	Print header information for application image
imxtract	Extract a part of a multi-image
interrupts	Enable or disable interrupts
itest	Return true/false on integer compare
loadb	Load binary file over serial line (kermit mode)
loads	Load S-Record file over serial line
loady	Load binary file over serial line (ymodem mode)
loop	Infinite loop on address range
md	Memory display
memmap	Displays memory map
mii	MII utility commands
mm	Memory modify (auto-incrementing address)
mmc	MMC sub system
mmcinfo	Display MMC info
moninit	Reset nvram, serial#, and write monitor to SPI flash
mtest	Simple RAM read/write test
mw	Memory write (fill)
nfs	Boot image through network using NFS protocol
nm	Memory modify (constant address)
pci	List and access PCI Configuration Space
pci_info	Show information about devices on PCI bus
ping	Send ICMP ECHO_REQUEST to network host

Table 5-1 MVME8100 Specific U-Boot Commands (continued)

Command	Description
printenv	Print environment variables
rarpboot	Boot image through network using RARP/TFTP protocol
reset	Perform RESET of the CPU
run	Run commands in an environment variable
saveenv	Save environment variables to persistent storage
script	Run a ';' delimited, ';' terminated list of commands
scsi	SCSI sub-system
scsiboot	Boot from SCSI device
setenv	Set environment variables
setexpr	Set environment variable as the result of eval expression
sf	SPI flash sub-system
showvar	Print local hushshell variables
sleep	Delay execution for some time
soft_reset	Soft reset the board
source	Run script from memory
test	Minimal test like /bin/sh
tftpboot	Boot image through network using TFTP protocol
tsi148	Initialize and configure Tundra Tsi148
usb	USB sub-system
usbboot	Boot from USB device
version	Print monitor version

5.5 Updating U-Boot

To update the U-Boot, place the image in the RAM (address 0x1000000 in this example) before copying it to the SPI flash.

The following procedure will replace the image in SPI bank 0:

1. Ensure FLASH_WP_N in SMT Configuration Switch (S3-1) is in the "OFF" position.
2. Select SPI flash # 0:
`sf probe 0`
3. Erase 0x90000 bytes starting at SPI address 0:
`sf erase 0 0x90000`
4. Write 0x90000 bytes from RAM address 0x1000000 starting at SPI address 0:
`sf write 0x1000000 0 0x90000`

To replace the image in SPI bank 1, replace step 2 with Select SPI flash # 1:

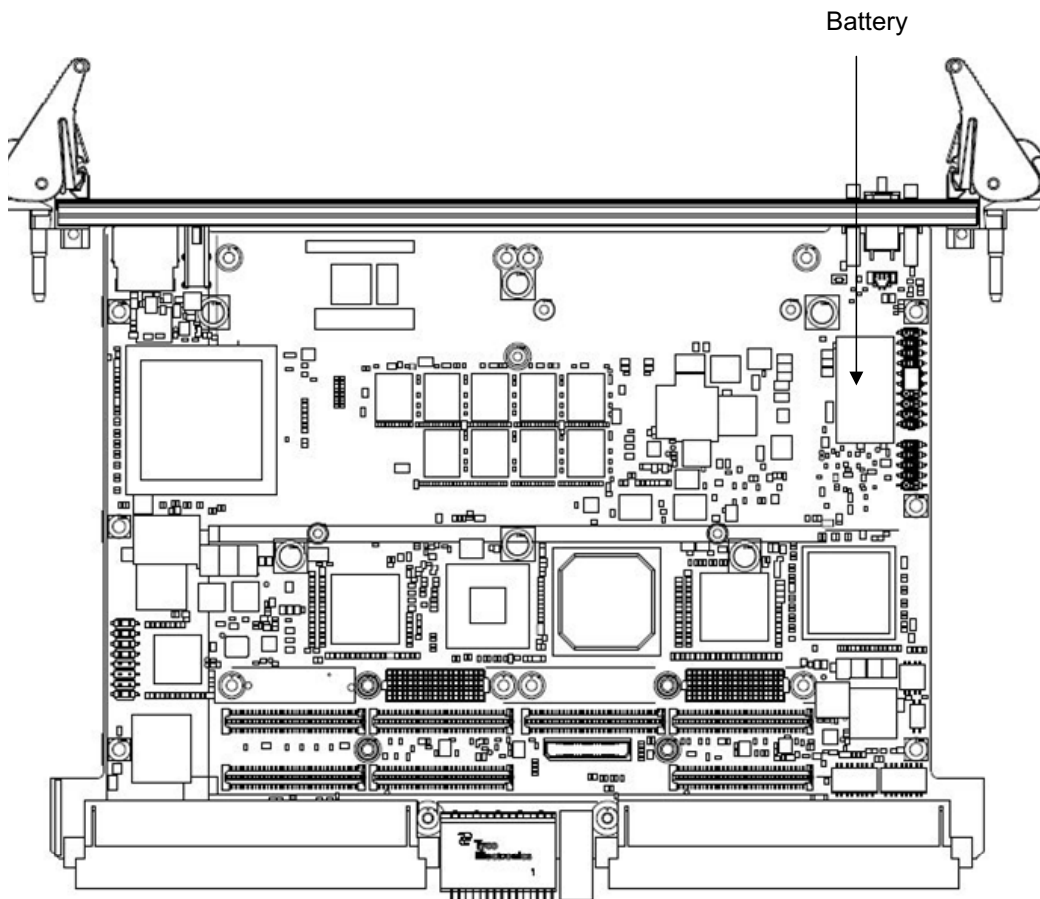
`sf probe 1`

Battery Exchange

A.1 Battery Exchange

The ENP1 variant contains an on-board battery. The battery location is shown in the following figure.

Figure A-1 Battery Location



The battery provides data retention of seven years summing up all periods of actual data use. Artesyn therefore assumes that there usually is no need to exchange the battery except, for example, in case of long-term spare part handling.

NOTICE

Board/System Damage

Incorrect exchange of lithium batteries can result in a hazardous explosion. When exchanging the on-board lithium battery, make sure that the new and the old battery are exactly the same battery models. If the respective battery model is not available, contact your local Artesyn sales representative for the availability of alternative, officially approved battery models.

Data Loss

Exchanging the battery can result in loss of time settings. Backup power prevents the loss of data during exchange. Quickly replacing the battery may save time settings.

Data Loss

If the battery has low or insufficient power the RTC is initialized. Exchange the battery before seven years of actual battery use have elapsed.

PCB and Battery Holder Damage

Removing the battery with a screw driver may damage the PCB or the battery holder. To prevent damage, do not use a screw driver to remove the battery from its holder.

Exchange Procedure

To exchange the battery, proceed as follows:

1. Remove the old battery.
2. Install the new battery with the plus sign (+) facing up.
3. Dispose of the old battery according to your country's legislation and in an environmentally safe way.

Related Documentation

B.1 Artesyn Embedded Technologies - Embedded Computing Documentation

The publications listed below are referenced in this manual. You can obtain electronic copies of Artesyn Embedded Technologies - Embedded Computing publications by contacting your local Artesyn sales office. For released products, you can also visit our Web site for the latest copies of our product documentation.

1. Go to www.artesyn.com/computing.
2. Under SUPPORT, click TECHNICAL DOCUMENTATION.
3. Under FILTER OPTIONS, click the Document types drop-down list box to select the type of document you are looking for.
4. In the Search text box, type the product name and click GO.

Table B-1 Artesyn Embedded Technologies - Embedded Computing Publications

Document Title	Publication Number
MVME8100 Programmer's Reference	6806800P28
MVME8100 Quick start Guide	6806800P26
MVME8100 Safety Notes Summary	6806800P27

B.2 Related Specifications

For additional information, refer to the following table for related specifications. As an additional help, a source for the listed document is provided. Please note that, while these sources have been verified, the information is subject to change without notice.

Table B-2 Related Specifications

Organization and Standard	Document Title
VITA Standards Organization	
VME64	ANSI/VITA 1-1994
VME64 Extensions	ANSI/VITA 1.1-1997
2eSST Source Synchronous Transfer	ANSI/VITA 1.5-2003

Table B-2 Related Specifications (continued)

Organization and Standard	Document Title
Processor PMC	ANSI/VITA 32-2003
PCI-X for PMC and Processor PMC	ANSI/VITA 39-2003
XMC Switched Mezzanine Card Auxiliary Standard, September 2005	VITA 42.0-2005
XMC PCI Express Protocol Layer Standard, June 2006	VITA 42.3-2006
Conduction Cooled PMC	ANSI/VITA 20 - 2001
PMC I/O Module (PIM) Draft Standard	VITA 36 Draft Rev 0.1 July 19, 1999
Universal Serial Bus	
Universal Serial Bus Specification	Revision 2.0 April 27, 2000
PCI Special Interest Group	
PCI Local Bus Specification, Revision 2.2	PCI Rev 2.2 December 18, 1998
PCI-X Electrical and Mechanical Addendum to the PCI Local Bus Specification, Revision 2.0a	PCI-X EM 2.0a August 22, 2003
PCI-X Protocol Addendum to the PCI Local Bus Specification, Revision 2.0a	PCI-X PT 2.0a July 22, 2003
Institute for Electrical and Electronics Engineers, Inc.	
IEEE Standard for a Common Mezzanine Card Family: CMC	IEEE1386 Oct 25, 2001
IEEE Standard Physical and Environmental Layer for PCI Mezzanine Cards: PMC	IEEE1386.1 Oct 25, 2001
Conduction cooled VME mechanics	IEEE 1101.2 - 1992
Additional Mechanical Specifications	IEEE 1101.10 - 1996
IEEE Standard for Mechanical Core Specifications for Microcomputers	IEEE 1101.1 - 1998

B.3 Manufacturers' Documents

For additional information, refer to the following table for manufacturers' data sheets or user's manuals. As an additional help, a source for the listed document is provided. Please note that, while these sources have been verified, the information is subject to change without notice.

Table B-3 Manufacturer's Publications

Document Title and Source	Publication Number
Freescall Corporation	
P5020/P5010 QorIQ Integrated Processor Hardware Specifications	P5020EC
P5020 QorIQ Integrated Multicore Communication Processor Reference Manual	P5020RM
Integrated Devices	
IDT 89HPES32NT24xG2 PCI Express Switch User Manual	
CPS-1616 User Manual	

Safety Notes

This section provides warnings that precede potentially dangerous procedures throughout this manual. Instructions contained in the warnings must be followed during all phases of operation, service, and repair of this equipment. You should also employ all other safety precautions necessary for the operation of the equipment in your operating environment. Failure to comply with these precautions or with specific warnings elsewhere in this manual could result in personal injury or damage to the equipment.

Artesyn intends to provide all necessary information to install and handle the product in this manual. Because of the complexity of this product and its various uses, we do not guarantee that the given information is complete. If you need additional information, ask your Artesyn Embedded Technologies representative.

This product is a Safety Extra Low Voltage (SELV) device designed to meet the EN60950-1 requirements for Information Technology Equipment. The use of the product in any other application may require safety evaluation specific to that application.

Only personnel trained by Artesyn or persons qualified in electronics or electrical engineering are authorized to install, remove or maintain the product.

The information given in this manual is meant to complete the knowledge of a specialist and must not be used as replacement for qualified personnel.

Keep away from live circuits inside the equipment. Operating personnel must not remove equipment covers. Only Factory Authorized Service Personnel or other qualified service personnel may remove equipment covers for internal subassembly or component replacement or any internal adjustment.

Do not install substitute parts or perform any unauthorized modification of the equipment or the warranty may be voided. Contact your local Artesyn Embedded Technologies representative for service and repair to make sure that all safety features are maintained.

EMC

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications.

Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense. Changes or modifications not expressly approved by Artesyn Embedded Technologies could void the user's authority to operate the equipment. Board products are tested in a representative system to show compliance with the above mentioned requirements. A proper installation in a compliant system will maintain the required performance. Use only shielded cables when connecting peripherals to assure that appropriate radio frequency emissions compliance is maintained.

Operation

Product Damage

High humidity and condensation on the board surface causes short circuits.

Do not operate the board outside the specified environmental limits.

Make sure the board is completely dry and there is no moisture on any surface before applying power.

Damage of Circuits

Electrostatic discharge and incorrect installation and removal can damage circuits or shorten their life.

Before touching the board or electronic components, make sure that you are working in an ESD-safe environment.

Board Malfunction

Switches marked as “reserved” might carry production-related functions and can cause the board to malfunction if their setting is changed.

Do not change settings of switches marked as “reserved”. The setting of switches which are not marked as “reserved” has to be checked and changed before board installation.

Installation

Data Loss

Powering down or removing a board before the operating system or other software running on the board has been properly shut down may cause corruption of data or file systems. Make sure all software is completely shut down before removing power from the board or removing the board from the chassis.

Product Damage

Only use injector handles for board insertion to avoid damage to the front panel and/or PCB. Deformation of the front panel can cause an electrical short or other board malfunction.

Product Damage

Inserting or removing modules with power applied may result in damage to module components.

Before installing or removing additional devices or modules, read the documentation that came with the product.

Cabling and Connectors

Product Damage

RJ-45 connectors on modules are either twisted-pair Ethernet (TPE) or E1/T1/J1 network interfaces. Connecting an E1/T1/J1 line to an Ethernet connector may damage your system.

- Make sure that TPE connectors near your working area are clearly marked as network connectors.
- Verify that the length of an electric cable connected to a TPE bushing does not exceed 100 meters.
- Make sure the TPE bushing of the system is connected only to safety extra low voltage circuits (SELV circuits).

If in doubt, ask your system administrator.

Battery

Board/System Damage

Incorrect exchange of lithium batteries can result in a hazardous explosion.

When exchanging the on-board lithium battery, make sure that the new and the old battery are exactly the same battery models. If the respective battery model is not available, contact your local Artesyn sales representative for the availability of alternative, officially approved battery models.

Data Loss

Exchanging the battery can result in loss of time settings. Backup power prevents the loss of data during exchange.

Quickly replacing the battery may save time settings.

Data Loss

If the battery has low or insufficient power the RTC is initialized.

Exchange the battery before seven years of actual battery use have elapsed.

PCB and Battery Holder Damage

Removing the battery with a screw driver may damage the PCB or the battery holder. To prevent damage, do not use a screw driver to remove the battery from its holder.

Dieses Kapitel enthält Hinweise, die potentiell gefährlichen Prozeduren innerhalb dieses Handbuchs vorrangestellt sind. Beachten Sie unbedingt in allen Phasen des Betriebs, der Wartung und der Reparatur des Systems die Anweisungen, die diesen Hinweisen enthalten sind. Sie sollten außerdem alle anderen Vorsichtsmaßnahmen treffen, die für den Betrieb des Produktes innerhalb Ihrer Betriebsumgebung notwendig sind. Wenn Sie diese Vorsichtsmaßnahmen oder Sicherheitshinweise, die an anderer Stelle dieses Handbuchs enthalten sind, nicht beachten, kann das Verletzungen oder Schäden am Produkt zur Folge haben.

Artesyn ist darauf bedacht, alle notwendigen Informationen zum Einbau und zum Umgang mit dem Produkt in diesem Handbuch bereit zu stellen. Da es sich jedoch um ein komplexes Produkt mit vielfältigen Einsatzmöglichkeiten handelt, können wir die Vollständigkeit der im Handbuch enthaltenen Informationen nicht garantieren. Falls Sie weitere Informationen benötigen sollten, wenden Sie sich bitte an die für Sie zuständige Geschäftsstelle von Artesyn.

Das Produkt wurde entwickelt, um die Sicherheitsanforderungen für SELV Geräte nach der Norm EN 60950-1 für informationstechnische Einrichtungen zu erfüllen. Die Verwendung des Produkts in einer anderen Anwendung erfordert eine Sicherheitsüberprüfung für diese spezifische Anwendung.

Einbau, Wartung und Betrieb dürfen nur von durch Artesyn ausgebildetem oder im Bereich Elektronik oder Elektrotechnik qualifiziertem Personal durchgeführt werden. Die in diesem Handbuch enthaltenen Informationen dienen ausschließlich dazu, das Wissen von Fachpersonal zu ergänzen, können dieses jedoch nicht ersetzen.

Halten Sie sich von stromführenden Leitungen innerhalb des Produktes fern. Entfernen Sie auf keinen Fall Abdeckungen am Produkt. Nur werksseitig zugelassenes Wartungspersonal oder anderweitig qualifiziertes Wartungspersonal darf Abdeckungen entfernen, um Komponenten zu ersetzen oder andere Anpassungen vorzunehmen.

Installieren Sie keine Ersatzteile oder führen Sie keine unerlaubten Veränderungen am Produkt durch, sonst verfällt die Garantie. Wenden Sie sich für Wartung oder Reparatur bitte an die für Sie zuständige Geschäftsstelle von Artesyn. So stellen Sie sicher, dass alle sicherheitsrelevanten Aspekte beachtet werden.

EMV

Das Produkt wurde in einem Artesyn Standardsystem getestet. Es erfüllt die für digitale Geräte der Klasse A gültigen Grenzwerte in einem solchen System gemäß den FCC-Richtlinien Abschnitt 15 bzw. EN 55022 Klasse A. Diese Grenzwerte sollen einen angemessenen Schutz vor Störstrahlung beim Betrieb des Produktes in Gewerbe- sowie Industriegebieten gewährleisten.

Das Produkt arbeitet im Hochfrequenzbereich und erzeugt Störstrahlung. Bei unsachgemäßem Einbau und anderem als in diesem Handbuch beschriebenen Betrieb können Störungen im Hochfrequenzbereich auftreten.

Wird das Produkt in einem Wohngebiet betrieben, so kann dies mit grosser Wahrscheinlichkeit zu starken Störungen führen, welche dann auf Kosten des Produktanwenders beseitigt werden müssen. Änderungen oder Modifikationen am Produkt, welche ohne ausdrückliche Genehmigung von Artesyn Embedded Technologies durchgeführt werden, können dazu führen, dass der Anwender die Genehmigung zum Betrieb des Produktes verliert.

Boardprodukte werden in einem repräsentativen System getestet, um zu zeigen, dass das Board den oben aufgeführten EMV-Richtlinien entspricht. Eine ordnungsgemässe Installation in einem System, welches die EMV-Richtlinien erfüllt, stellt sicher, dass das Produkt gemäss den EMV-Richtlinien betrieben wird. Verwenden Sie nur abgeschirmte Kabel zum Anschluss von Zusatzmodulen. So ist sichergestellt, dass sich die Aussendung von Hochfrequenzstrahlung im Rahmen der erlaubten Grenzwerte bewegt.

Warnung! Dies ist eine Einrichtung der Klasse A. Diese Einrichtung kann im Wohnbereich Funkstörungen verursachen. In diesem Fall kann vom Betreiber verlangt werden, angemessene Maßnahmen durchzuführen.

Betrieb

1 Beschädigung des Produktes

Hohe Luftfeuchtigkeit und Kondensat auf der Oberfläche des Produktes können zu Kurzschlüssen führen.

Betreiben Sie das Produkt nur innerhalb der angegebenen Grenzwerte für die relative Luftfeuchtigkeit und Temperatur. Stellen Sie vor dem Einschalten des Stroms sicher, dass sich auf dem Produkt kein Kondensat befindet.

Beschädigung von Schaltkreisen

Elektrostatische Entladung und unsachgemäßer Ein- und Ausbau des Produktes kann Schaltkreise beschädigen oder ihre Lebensdauer verkürzen.

Bevor Sie das Produkt oder elektronische Komponenten berühren, vergewissern Sie sich, daß Sie in einem ESD-geschützten Bereich arbeiten.

Fehlfunktion des Produktes

Schalter, die mit 'Reserved' gekennzeichnet sind, können mit produktionsrelevanten Funktionen belegt sein. Das Ändern dieser Schalter kann im normalen Betrieb Störungen auslösen.

Verstellen Sie nur solche Schalter, die nicht mit 'Reserved' gekennzeichnet sind. Prüfen und ggf. ändern Sie die Einstellungen der nicht mit 'Reserved' gekennzeichneten Schalter, bevor Sie das Produkt installieren.

Installation

Datenverlust

Das Herunterfahren oder die Deinstallation eines Boards bevor das Betriebssystem oder andere auf dem Board laufende Software ordnungsmässig beendet wurde, kann zu partiellem Datenverlust sowie zu Schäden am Filesystem führen.

Stellen Sie sicher, dass sämtliche Software auf dem Board ordnungsgemäss beendet wurde, bevor Sie das Board herunterfahren oder das Board aus dem Chassis entfernen.

Beschädigung des Produktes

Fehlerhafte Installation des Produktes kann zu einer Beschädigung des Produktes führen.

Verwenden Sie die Handles, um das Produkt zu installieren/deinstallieren. Auf diese Weise vermeiden Sie, dass das Face Plate oder die Platine deformiert oder zerstört wird.

Beschädigung des Produktes und von Zusatzmodulen

Fehlerhafte Installation von Zusatzmodulen, kann zur Beschädigung des Produktes und der Zusatzmodule führen.

Lesen Sie daher vor der Installation von Zusatzmodulen die zugehörige Dokumentation.

Kabel und Stecker

Beschädigung des Produktes

Bei den RJ-45-Steckern, die sich an dem Produkt befinden, handelt es sich entweder um Twisted-Pair-Ethernet (TPE) oder um E1/T1/J1-Stecker. Beachten Sie, dass ein versehentliches Anschließen einer E1/T1/J1-Leitung an einen TPE-Stecker das Produkt zerstören kann.

- Kennzeichnen Sie deshalb TPE-Anschlüsse in der Nähe Ihres Arbeitsplatzes deutlich als Netzwerkanschlüsse.
- Stellen Sie sicher, dass die Länge eines mit Ihrem Produkt verbundenen TPE-Kabels 100 m nicht überschreitet.
- Das Produkt darf über die TPE-Stecker nur mit einem Sicherheits-Kleinspannungs-Stromkreis (SELV) verbunden werden.

Bei Fragen wenden Sie sich an Ihren Systemverwalter.

Batterie

Beschädigung des Blades

Ein unsachgemäßer Einbau der Batterie kann gefährliche Explosionen und

Beschädigungen des Blades zur Folge haben.

Verwenden Sie deshalb nur den Batterietyp, der auch bereits eingesetzt wurde und

befolgen Sie die Installationsanleitung.

Datenverlust

Wenn Sie die Batterie austauschen, können die Zeiteinstellungen verloren gehen. Eine Backupversorgung verhindert den Datenverlust während des Austauschs.

Wenn Sie die Batterie schnell austauschen, bleiben die Zeiteinstellungen möglicherweise erhalten.

Datenverlust

Wenn die Batterie wenig oder unzureichend mit Spannung versorgt wird, wird der RTC initialisiert.

Tauschen Sie die Batterie aus, bevor sieben Jahre tatsächlicher Nutzung vergangen sind.

Schäden an der Platine oder dem Batteriehalter

Wenn Sie die Batterie mit einem Schraubendreher entfernen, können die Platine oder der Batteriehalter beschädigt werden.

Um Schäden zu vermeiden, sollten Sie keinen Schraubendreher zum Ausbau der Batterie verwenden.

Umweltschutz

Entsorgen Sie alte Batterien und/oder Blades/Systemkomponenten/RTMs stets gemäß der in Ihrem Land gültigen Gesetzgebung, wenn möglich immer umweltfreundlich.



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